



# Study of various configurations of Micro Hollow Cathode Discharges in Ar/N<sub>2</sub> used for boron nitride PECVD

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Joint GEC-IOPS / OLTPD seminar – March 7, 2023

# Team in LSPM

- Colleagues:

Xavier Aubert, Ovidiu Brinza, Kristaq Gazeli, Laurent Invernizzi, Guillaume Lombardi, Vianney Mille, Swaminathan Prasanna, Alexandre Tallaire, Ludovic William

- Post-docs:

- Hiba Kabbara (2018-2019)
- Manoel Jacquemin (2021-2022)



- PhD students:

- Salima Kasri (2015-2019)
- **Alice Remigy (2019 – 2022)**
- Belkacem Menacer (2022 - )



# Collaborations

- Colleagues from LPGP: Gérard Beauville, Michel Fleury, Stéphane Pasquiers, Joao Santos Sousa



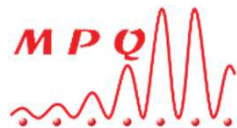
- Colleagues from synchrotron SOLEIL: Nelson de Oliveira and Laurent Nahon



- Colleagues from LTM and LIPhy: Nader Sadeghi



- Colleagues from MPQ: Clément Barraud and Maria Luisa Della Rocca



# Agenda of the presentation

- I. Introduction
- II. Deposition of boron nitride by PECVD: description of the process and few deposition results
- III. Atomic nitrogen production in the microplasma source
- IV. Atomic nitrogen transport in the deposition chamber
- V. Conclusion and perspectives



# My laboratory: LSPM

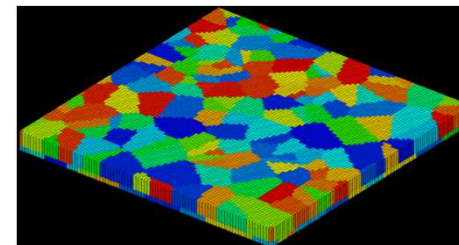


- Laboratory of Process and Material Sciences; created January 1<sup>st</sup>, 2011
- Located in France, in the north of Paris



# LSPM: few numbers

- 85 permanent positions:
  - 10 CNRS researchers
  - 55 associated professors/professors
  - 20 engineers/technicians/administrators
- 45 PhD students and post-docs
- 4/5 PhD government grants/year



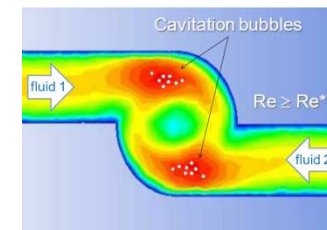
# LSPM: scientific axis

- 3 scientific axis:

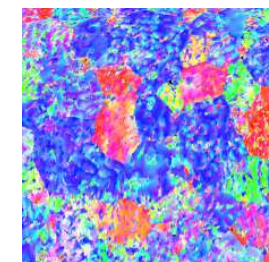
- 1) Development of elaboration and transformation process of materials



- 2) Structural characteristics and properties of materials



- 3) Integration of materials in systems, devices and process





# University Sorbonne Paris Nord





# University Sorbonne Paris Nord

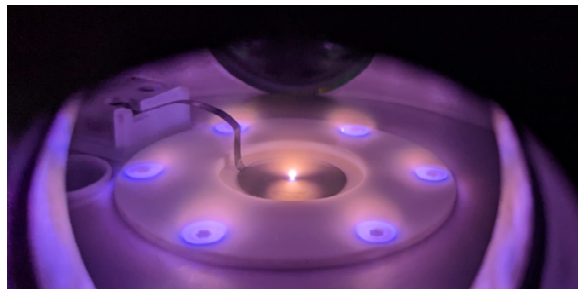


# University Sorbonne Paris Nord

- 5 campus
- 26000 students
- 28 laboratories
- 1500 assistant professors and professors
- 730 people in the administration and technical staff



# Deposition of Boron Nitride by microplasmas: process description





# Context

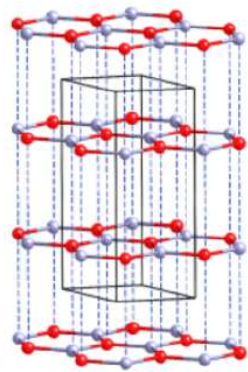
- New research axis since 2016 in LSPM: “Microplasmas for innovative materials”.
- Idea: choice of a material and a versatile process
  - control of the morphological and structural characteristics of the films
- Goals:
  - To develop an efficient new plasma reactor for the deposition of high potential materials on large surfaces, easily adaptable to established technologies
  - To optimize the quality of the deposited layers by understanding the mechanisms involved in growth processes using reactive plasmas
- Target material: hexagonal boron-nitride (h-BN)



# Why h-BN?

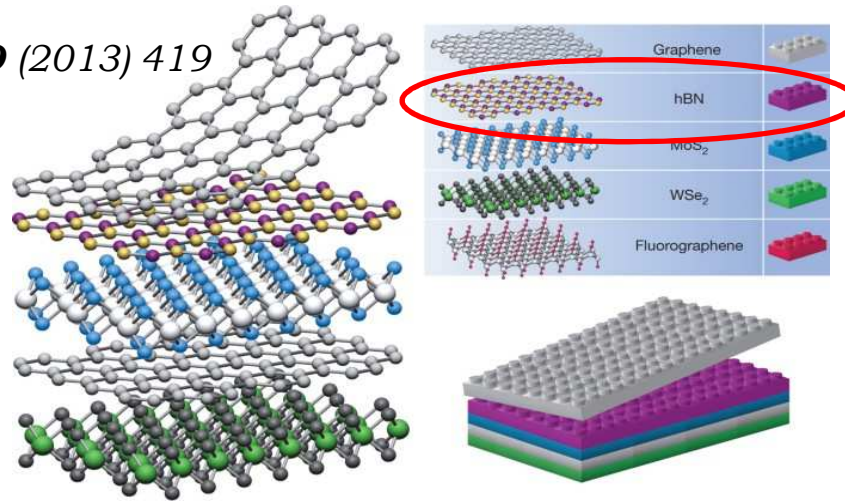
- Large band gap, thermally and chemically stable, ideal substrate for graphene.

*Griem et al. Nature* **499** (2013) 419



● Boron  
● Nitrogen

h-BN ( $sp^2$ )

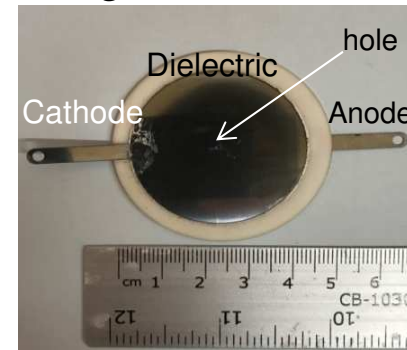
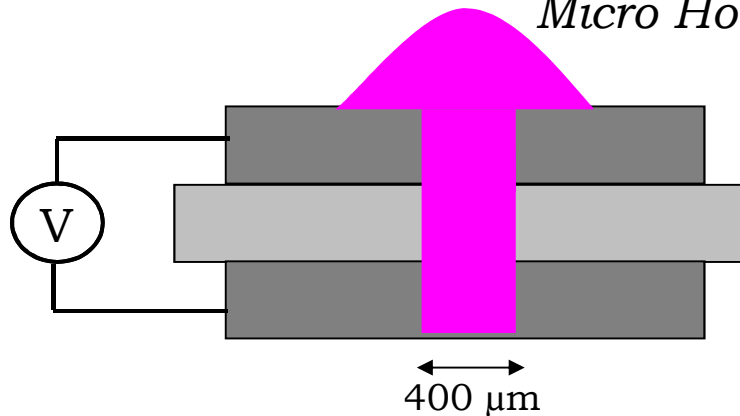


*Van der Waals heterostructures*

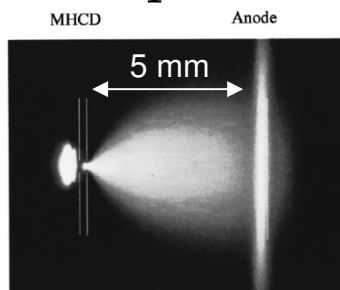
- Strategic material highly demanded for electronic and optoelectronic applications, also quantum technologies.
- But the development of applications based on this material is still held back by the poor availability of high-quality epitaxial films on large areas → new process based on microplasmas.

# Why MHCD?

## Micro Hollow Cathode Discharges

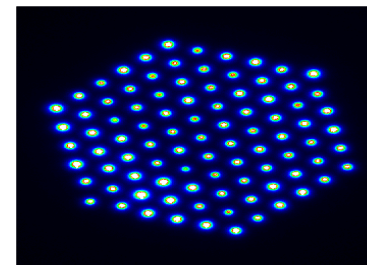


- Low temperature plasma: reduction of the deposition temperature compared to conventional processes.
- Production of high electron density: high degree of dissociation of nitrogen.
- Deposition on large surfaces: MCSD and array of MHCDs.



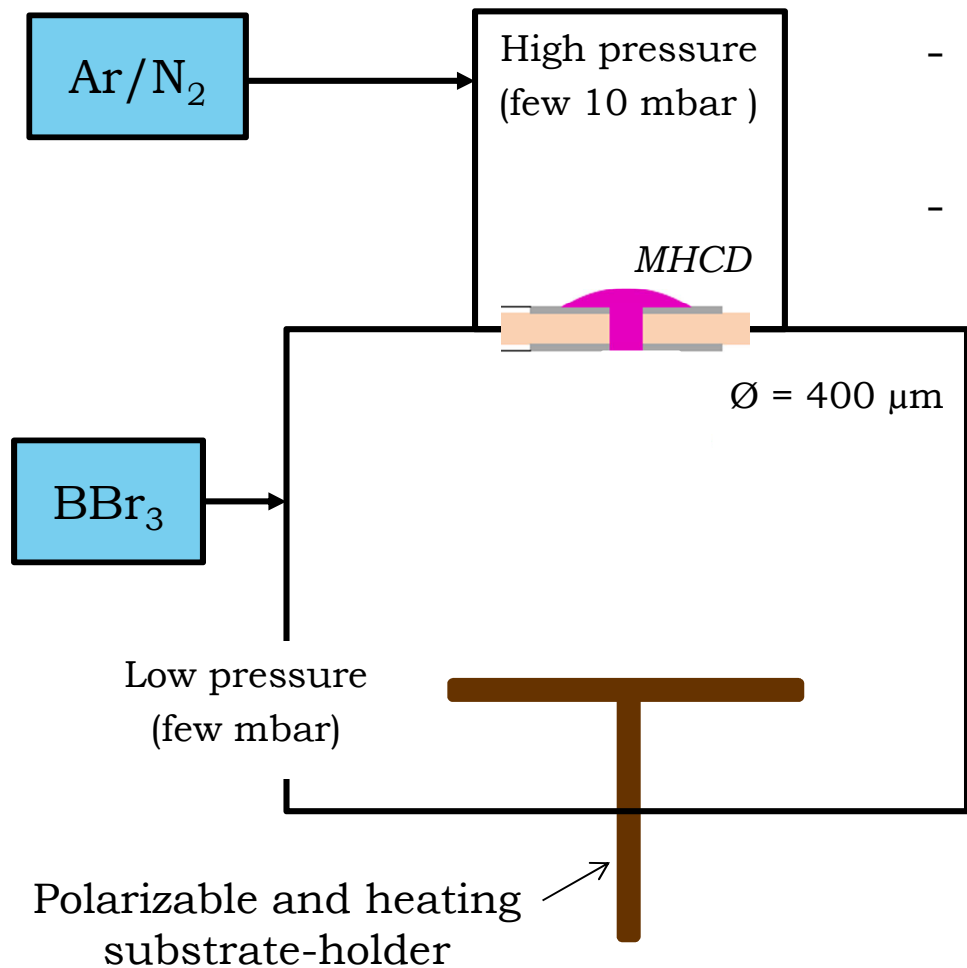
Ar  
160 Torr

*Stark et al. PPCF* **85** (1999) 2075  
*Makasheva et al. PPCF* **49** (2007) B233

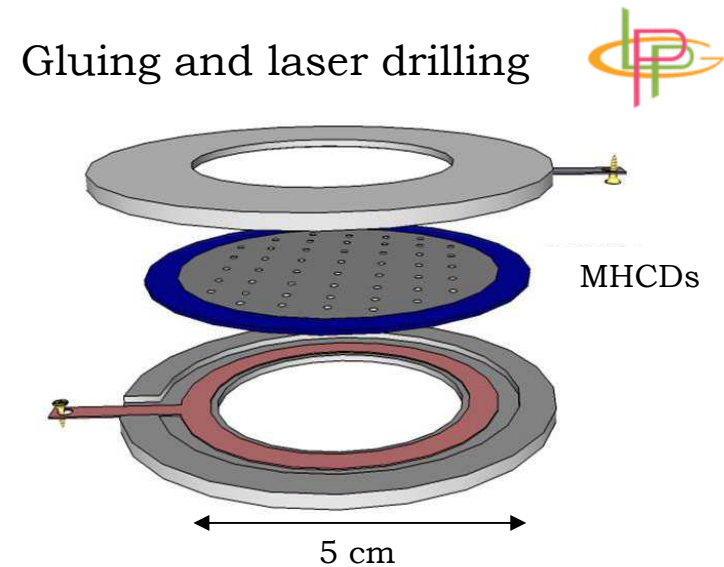


Pulsed  
power supply  
*91 MHCDs in pure N<sub>2</sub>*

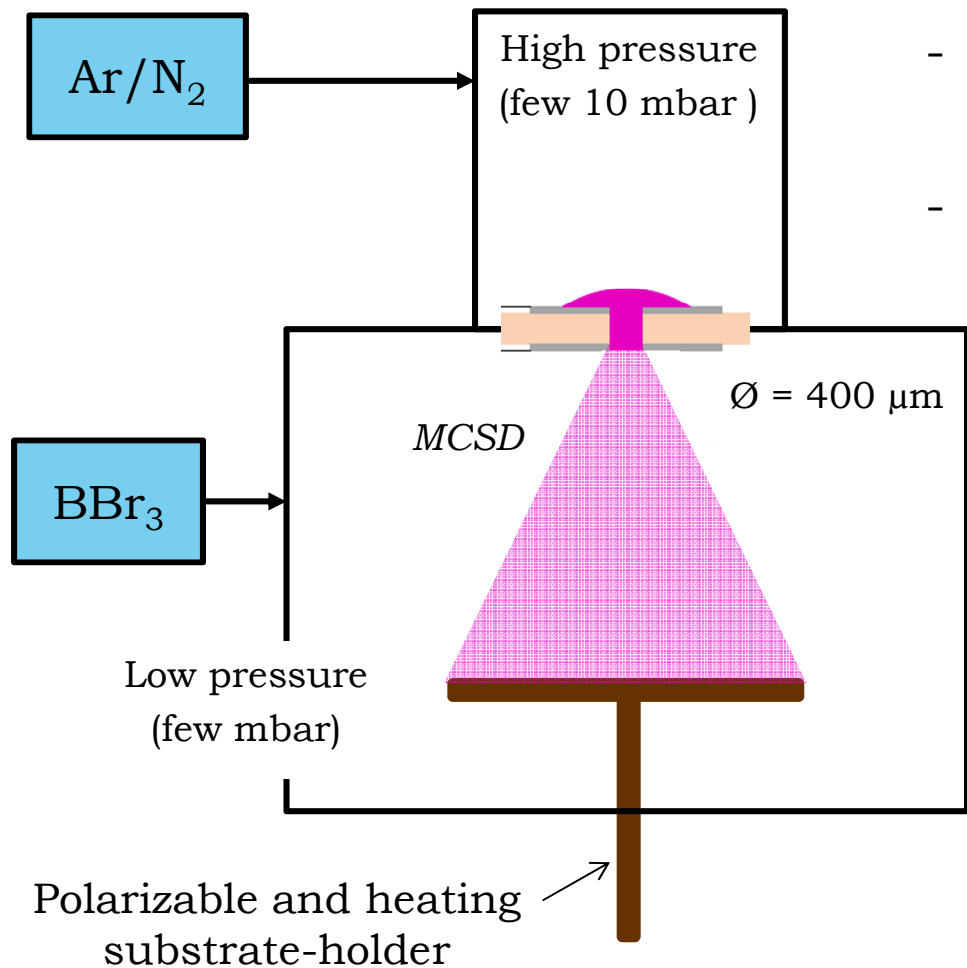
# PECVD process



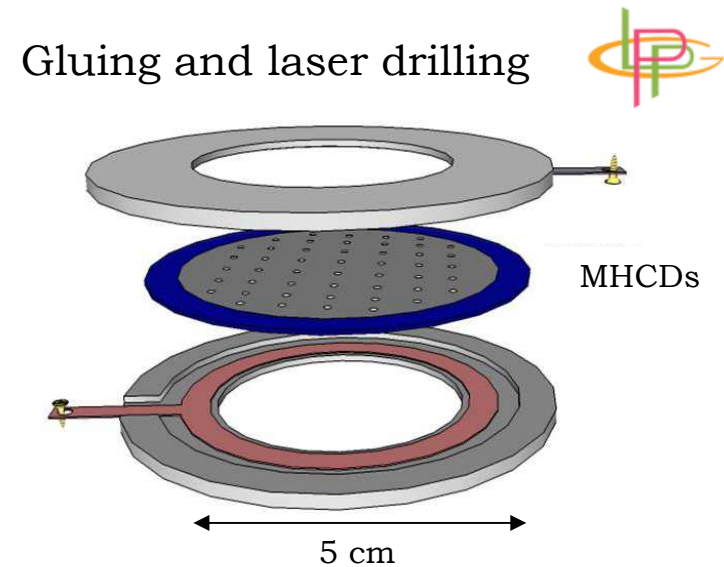
- Higher pressure upstream chamber  
→ dissociation of N<sub>2</sub>
- Lower pressure downstream chamber  
→ limitation of N recombination



# PECVD process



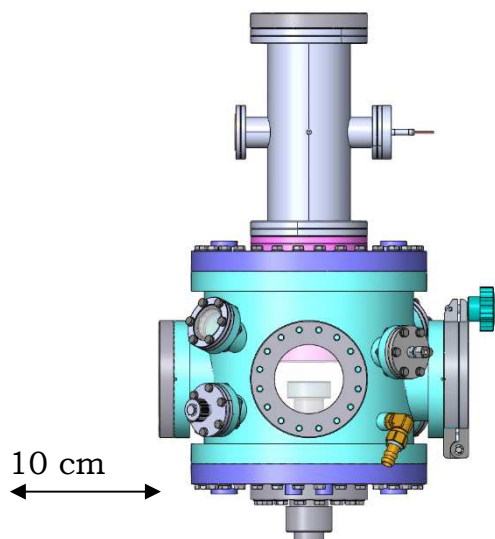
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# Developed reactors

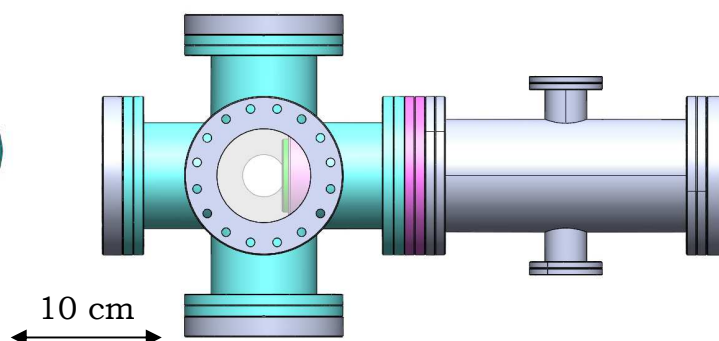
Deposition reactor



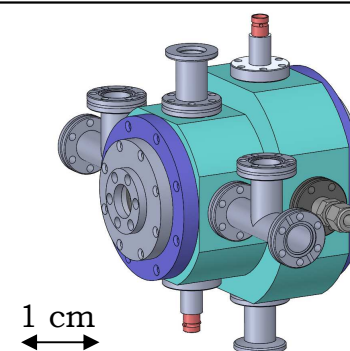
Design of the pulsed power supply

Optimal plasma conditions for deposition

Matrix reactor



1 MHCD reactor



## h-BN deposition

Excitation by a ns pulsed high voltage

Ar/N<sub>2</sub> discharge + boron precursor : BBr<sub>3</sub>

## Optimization of a MHCD matrix

Excitation by a ns pulsed high voltage

Ar/N<sub>2</sub> discharge

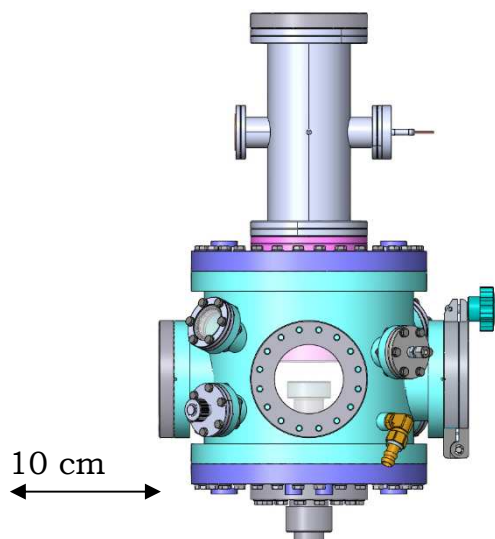
## Fundamental study of one MHCD in reactive gas

DC excitation

Ar/N<sub>2</sub> discharge

# Developed reactors

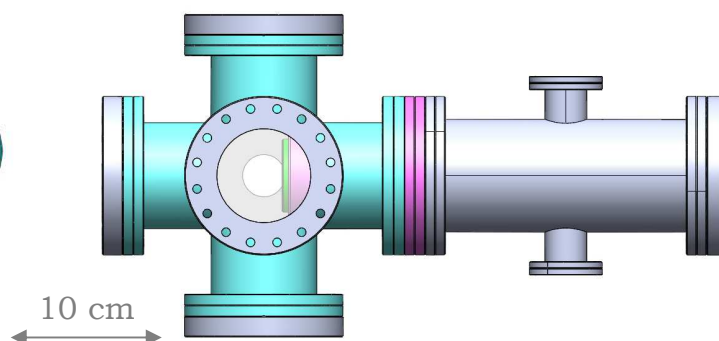
Deposition reactor



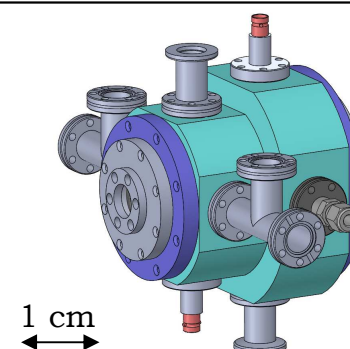
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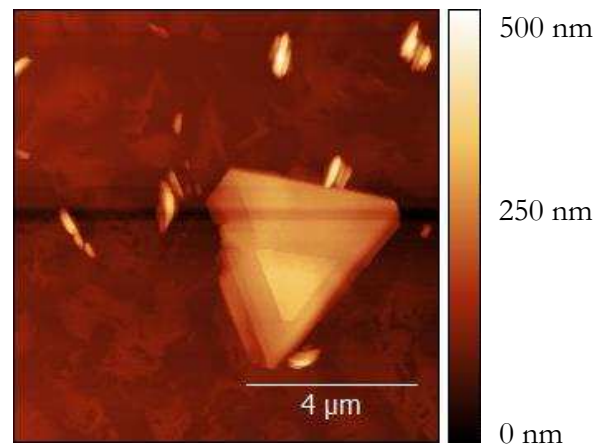
Ar/N<sub>2</sub> discharge

## Fundamental study of one MHCD in reactive gas

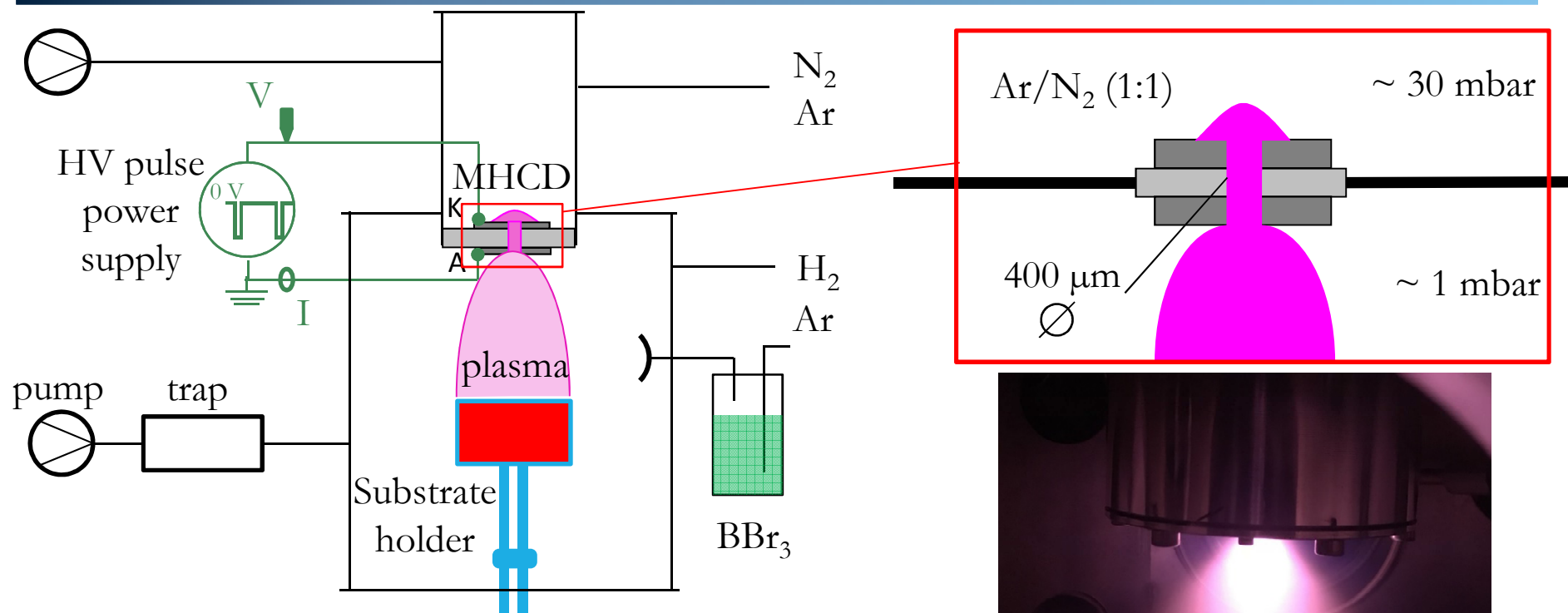
DC excitation

Ar/N<sub>2</sub> discharge

# Deposition reactor: few results



# Experimental setup for h-BN deposition



## Working conditions :

Pulse 1 kV, 500 ns, 10 kHz, 71-120 μJ/pulse

BBr<sub>3</sub> flux: 2 μmol/sec

V<sub>SH</sub>: 230 V and T<sub>SH</sub>: 600-950°C

P<sub>deposition chamber</sub> : 0.7-1.2 mbar

Substrates: (0001) sapphire, (111) or (100) Si

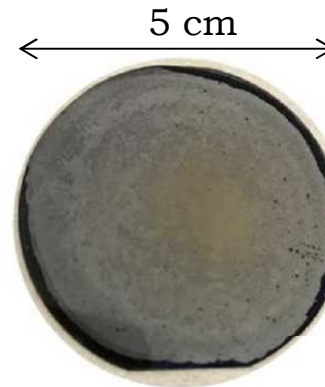


Expansion covering  
all the substrate



# Deposition results

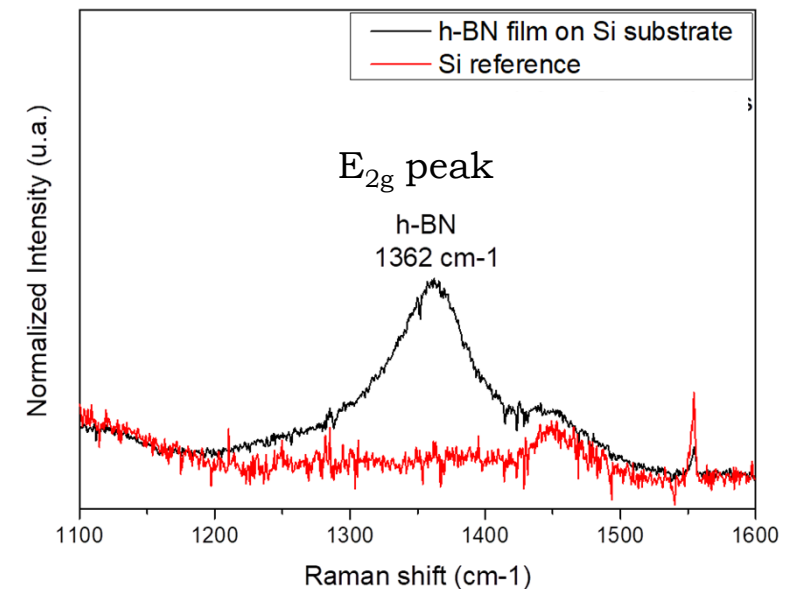
- Deposition on 2-inch silicon (Duration: 2-7h)
- Clear signature of h-BN at  $1362\text{ cm}^{-1}$   $\Rightarrow$  Proof of feasibility
- Deposition rate:  $v \sim 35\text{ nm/h}$
- Crystalline quality probably moderate considering the broad Raman line at half maximum
- Chemical composition: 55% of B and 45% of N (very close concentration)
- Effect of the distance MHCD/substrate



Film deposited on 2-inch Si wafer covering almost all the surface

*Photography*

**Raman spectroscopy :**

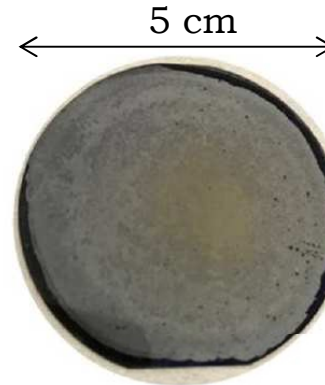


*H. Kabbara et al, APL 116 (2020) 171902*

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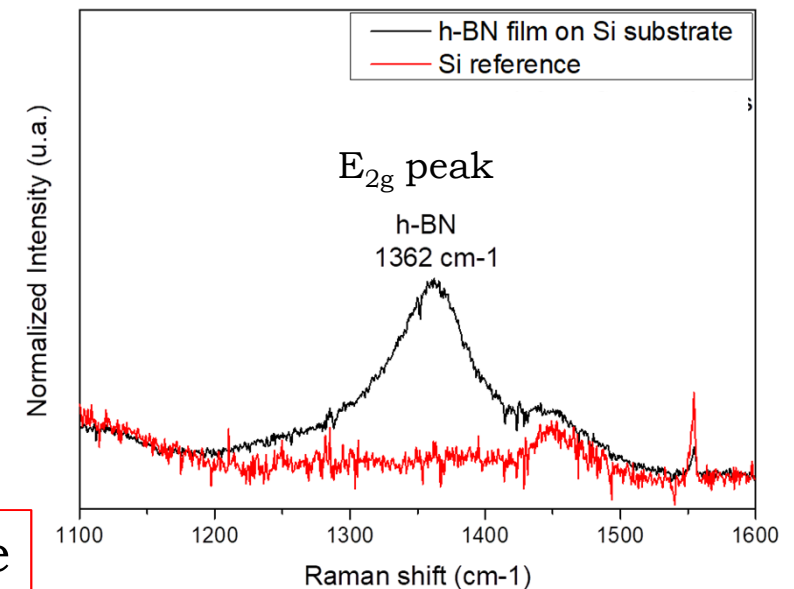
Optimisation of the process  $\rightarrow$  study of the discharge: density of N in particular



Film deposited on 2-inch Si wafer covering almost all the surface

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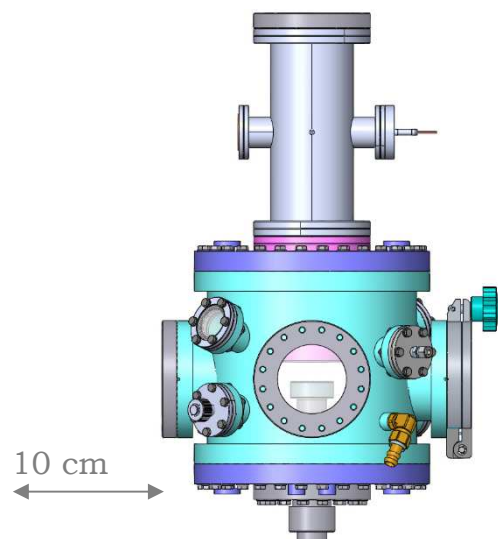
Raman spectroscopy :



*H. Kabbara et al, APL 116 (2020) 171902*

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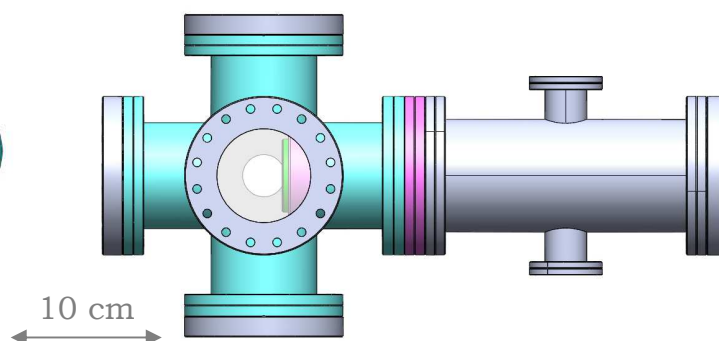
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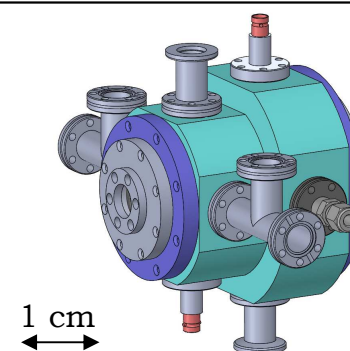
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*Alice Remigy thesis*

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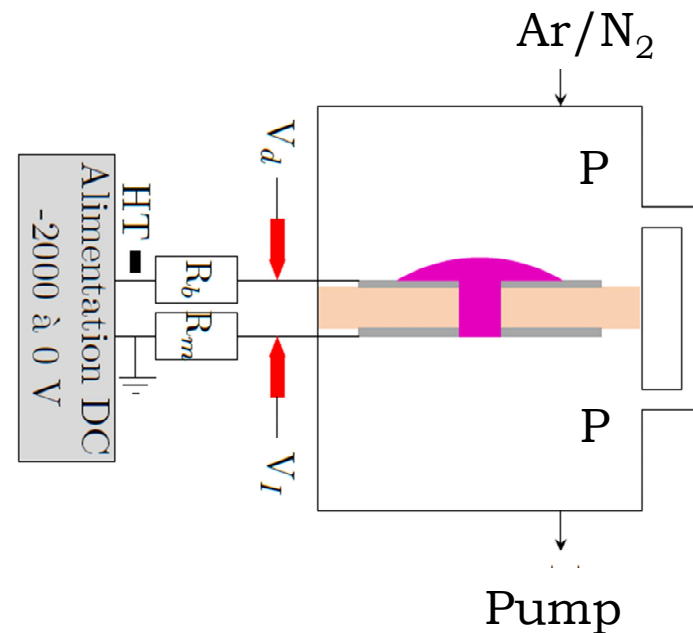
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# Study of the 1 MHCD reactor: production of atomic nitrogen

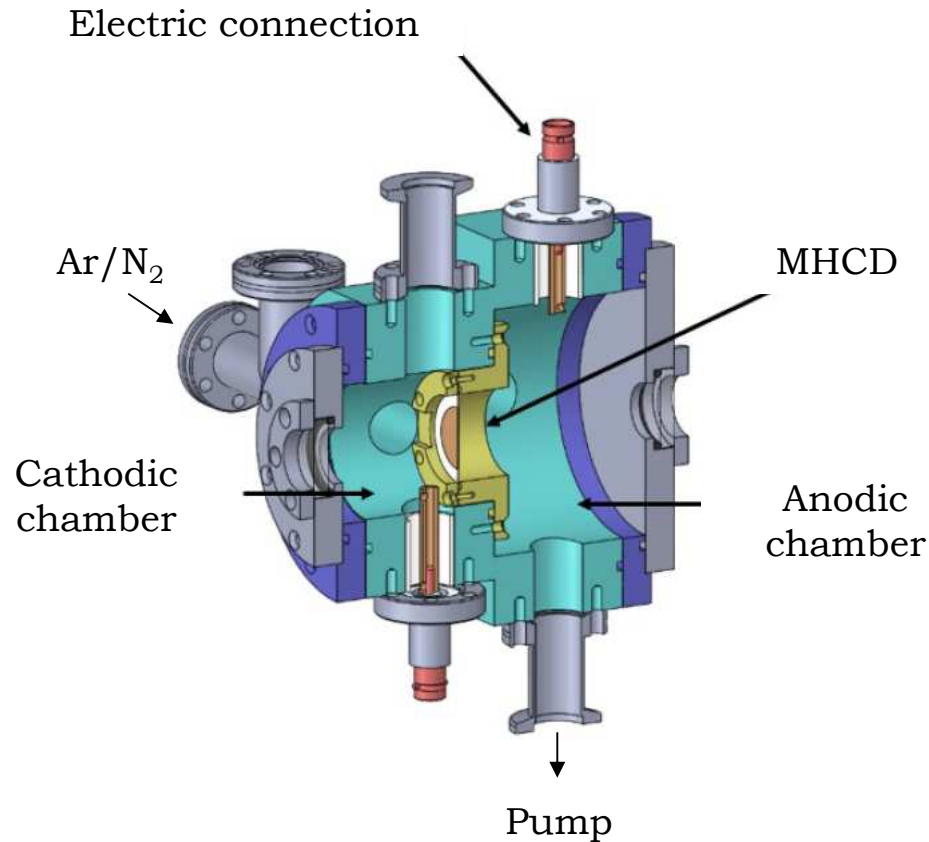
*MHCD configuration*



*Same pressure in the  
two chambers of the  
reactor*



# Tools



- Electrical characterization → discharge resistance
- VUV Fourier transform absorption spectro. (SOLEIL synchrotron) and TALIF → atomic nitrogen density

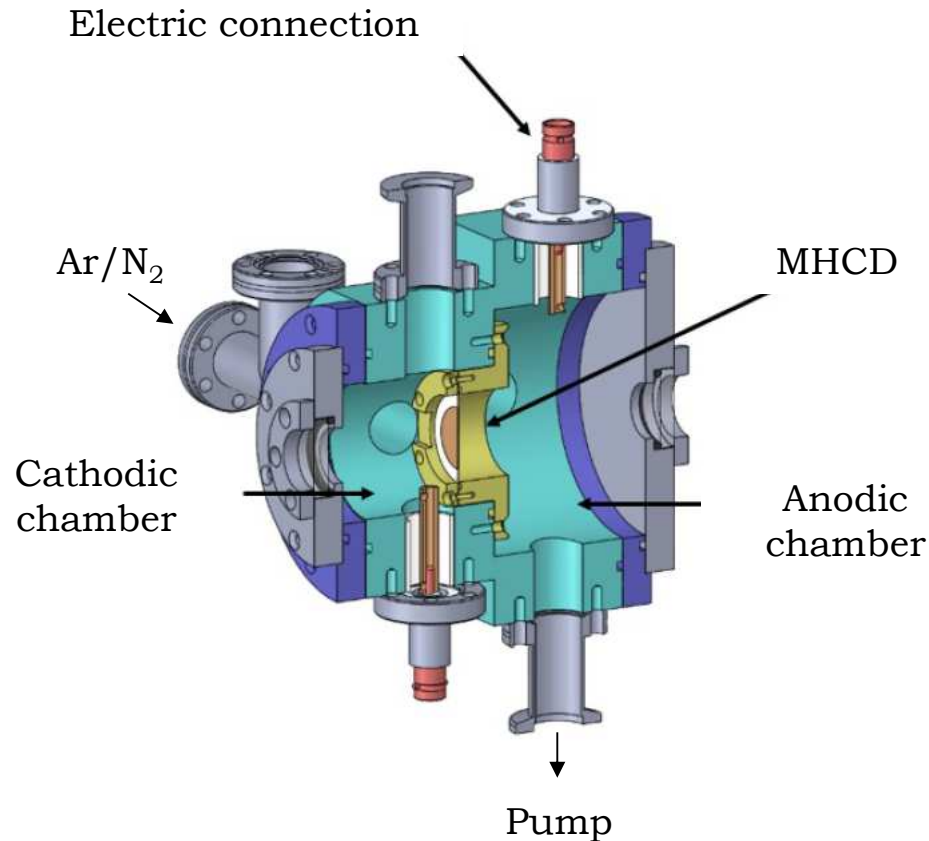


- OES → electron density and gas temperature
- Absorption spectroscopy → metastable argon density



- Global model 0D

# Tools



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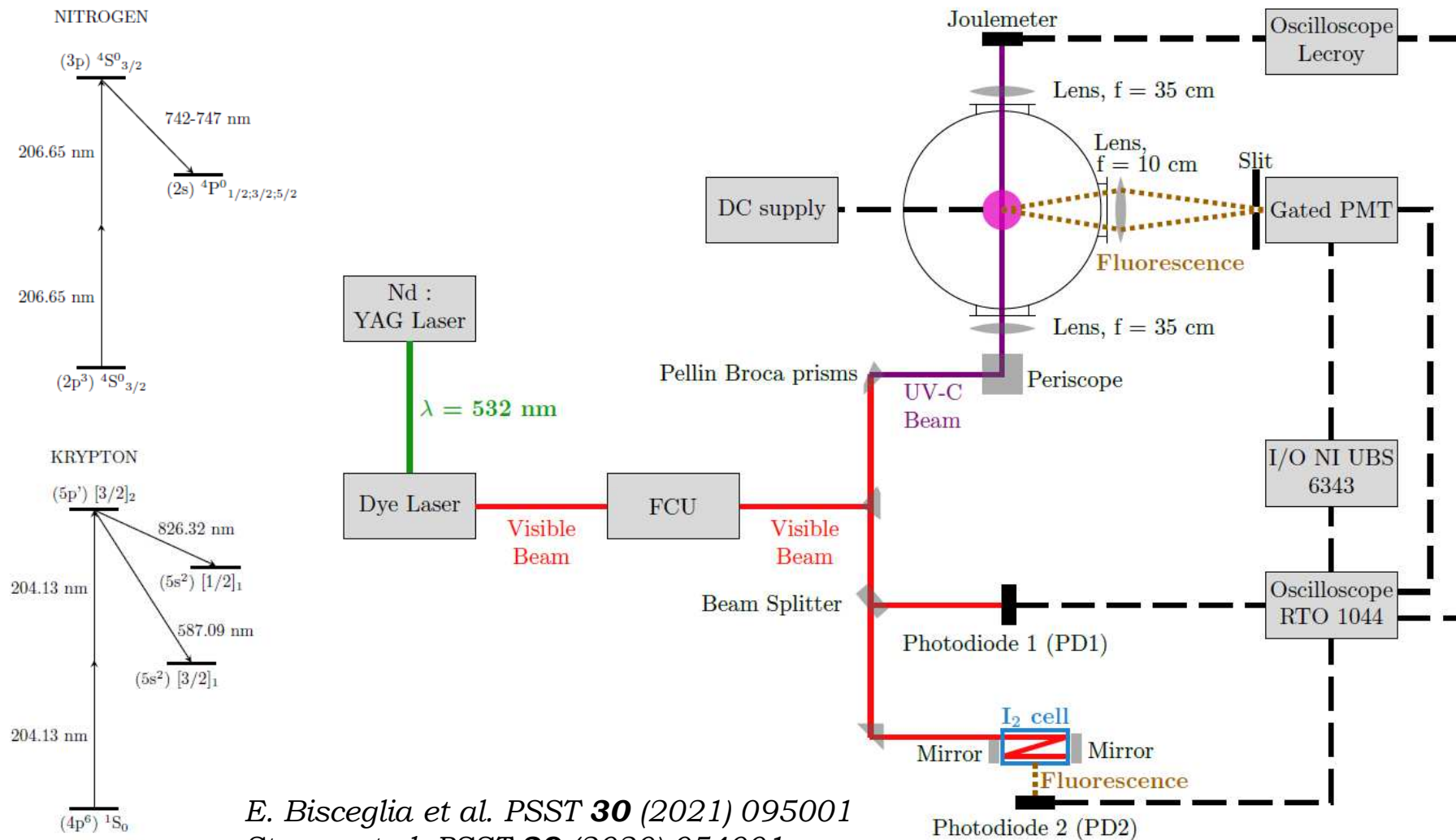


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- Global model 0D

# Two photon Absorption Laser Induced Fluorescence (TALIF)

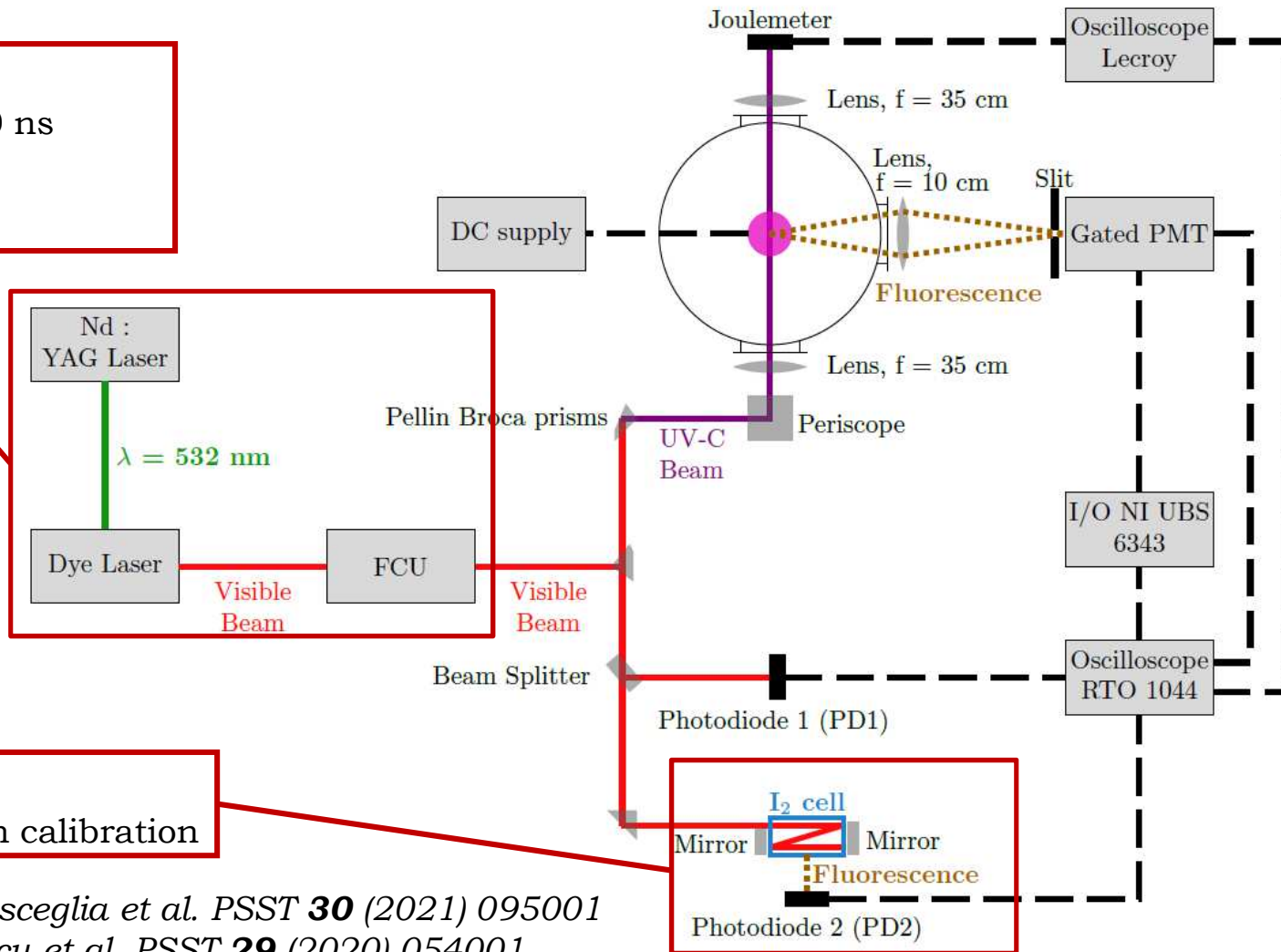


*E. Bisceglia et al. PSST 30 (2021) 095001*  
*Stancu et al. PSST 29 (2020) 054001*

# Two photon Absorption Laser Induced Fluorescence (TALIF)

## ns-Laser

- Pulse width : 10 ns
- 10 Hz
- 2.5 mJ/pulse



## Iodine cell

- Wavelength calibration

*E. Bisceglia et al. PSST 30 (2021) 095001*  
*Stancu et al. PSST 29 (2020) 054001*



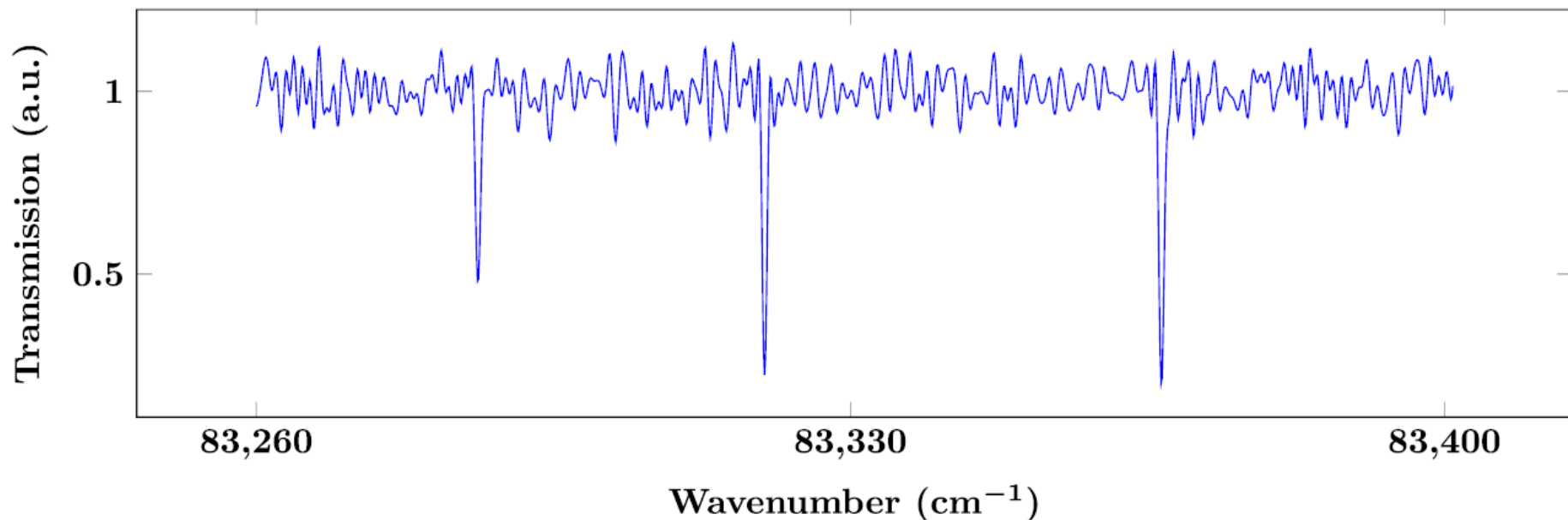
# Fourier transform absorption spectroscopy (FTS VUV)

- Direct measurement of N in the ground state studying the transitions in the vacuum UV.



*K. Niemi et al. APL* **103** (2013) 034102  
*Dumitrache et al. PSST* **31** (2022) 015004

- Probed transition (120 nm): N ( $2p^3\ ^4S_{3/2}$ )  $\rightarrow$  Triplet N ( $3s\ ^4P_{1/2, 3/2, 5/2}$ )



Example of a normalized non deconvoluted transmission spectrum

# Global model

- Volume-averaged (0D) model: temporal variations of volume-averaged quantities (densities and temperature)
- Particle balance:

$$\frac{dn_{\alpha}}{dt} = G_{\alpha} - P_{\alpha}$$

- Electron power balance:

$$\frac{d}{dt} \left( \frac{3}{2} n_e e T_e \right) = P_{\text{abs}} - P_{\text{dis}}$$

# Global model

Power balance:

Modélisation of the cathodic region

$$P_{\text{abs}} = \frac{A}{S_C} \kappa I_d V_d$$

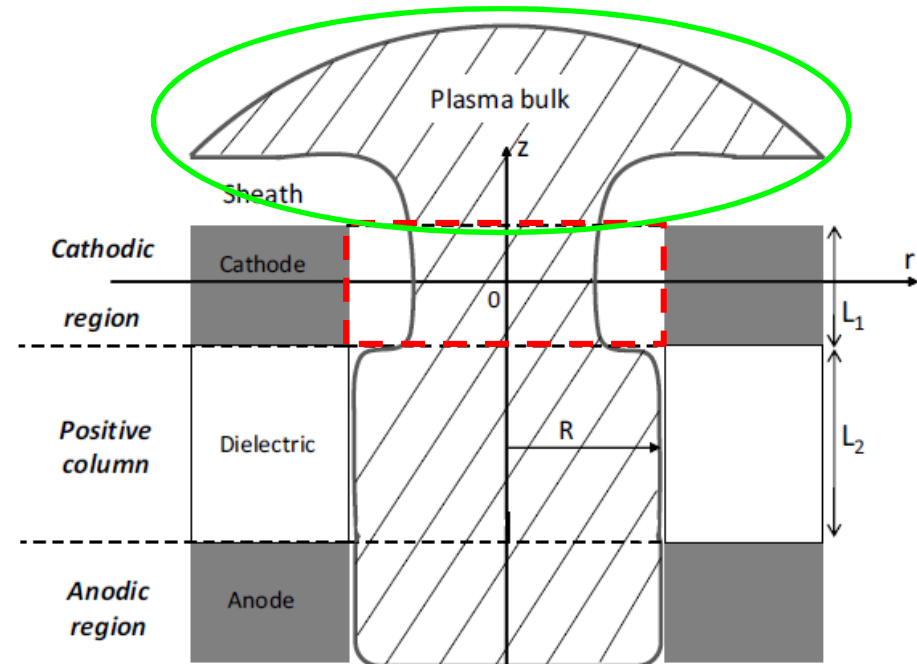
Fraction of power absorbed by the electrons:

$$\kappa = \frac{\bar{P}_e}{\bar{P}_e + \bar{P}_i} \approx \frac{1}{1 + \gamma} \frac{1}{\ln(1 + \frac{1}{\gamma})}$$

Particle balance:

Electropositive plasma: Ar-N<sub>2</sub> mixture

- 14 species
- 69 volume reactions
- T<sub>g</sub>=470 K



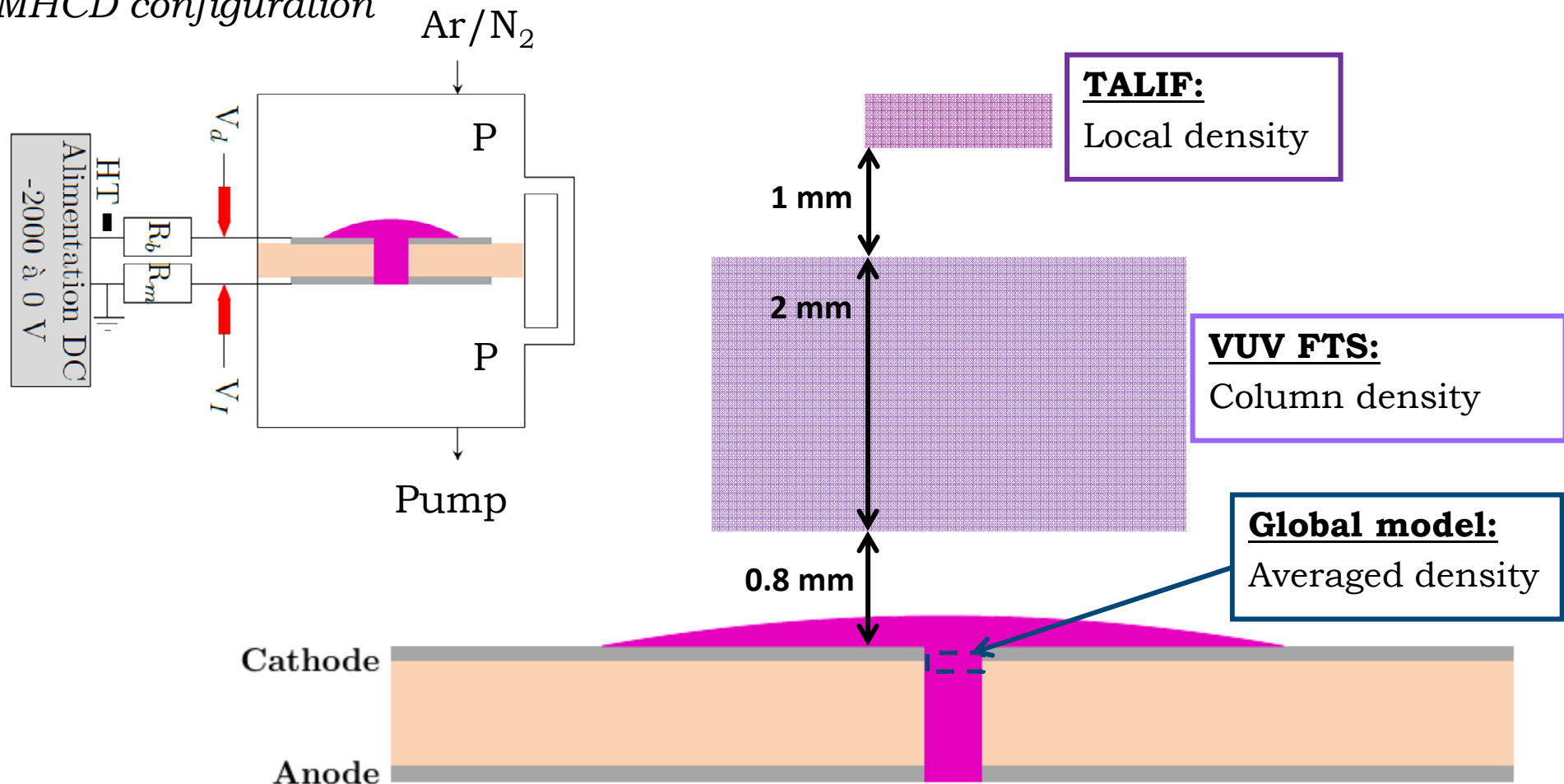
C. Lazzaroni et al. PSST **20** (2011) 055004

14 considered species:

Ar, Ar<sup>+</sup>, Ar<sub>2</sub><sup>+</sup>, Ar<sup>m</sup>, Ar<sup>r</sup>, Ar<sup>4p</sup>,  
 N<sub>2</sub>, N, N<sub>2</sub><sup>+</sup>, N<sub>4</sub><sup>+</sup>, N<sub>2</sub>(A), N<sub>2</sub>(B),  
 N<sub>2</sub>(C) and e<sup>-</sup>

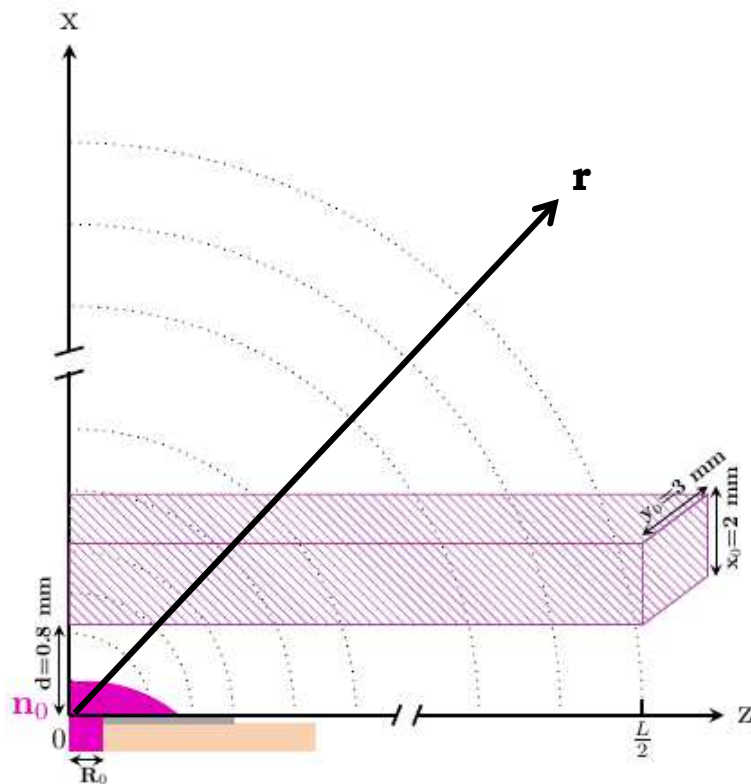
# Experiments / model comparison?

MHCD configuration



# Model of diffusion: $n(r)$

- VUV FTS measurements: estimation of the absorption length to get the N density from the column density
- Comparison of  $n_N$  measurements by FTS and TALIF



Diffusion equation and N atom conservation equation:

$$\Gamma(r) = -D \frac{\partial n(r)}{\partial r} \quad \text{div} \vec{\Gamma} = 0$$

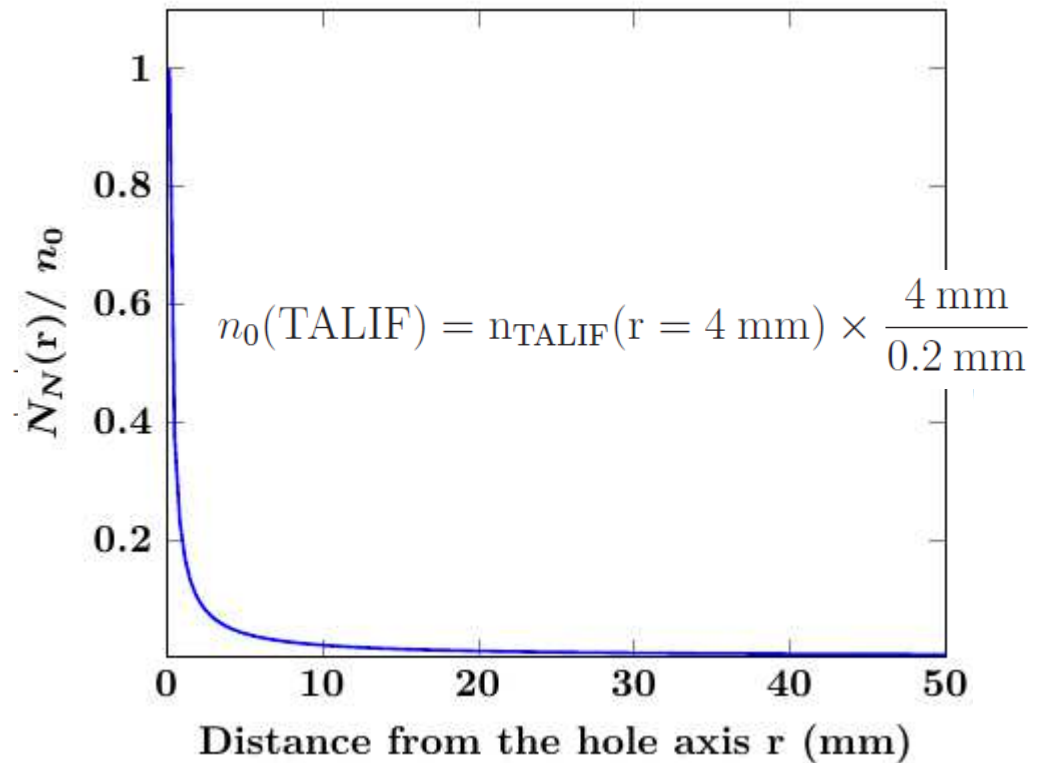
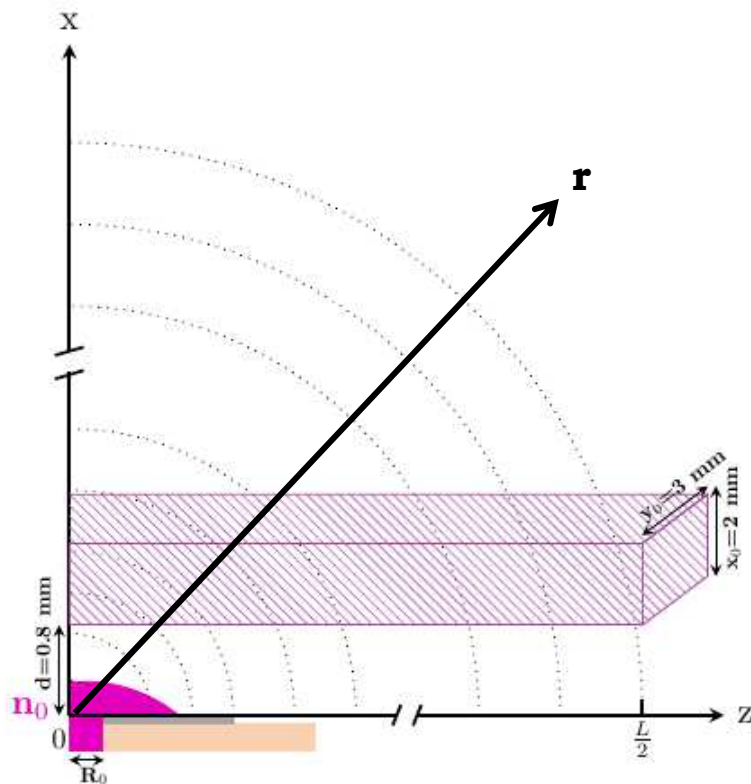
$$n(r) = \frac{R_0 n_0}{r}$$



# Model of diffusion: $n(r)$

→ VUV FTS measurements: estimation of the absorption length to get the N density from the column density

→ Comparison of  $n_N$  measurements by FTS and TALIF



# Model of diffusion: eff. absorption length

- Density in cartesian coordinates:  $n(x, y, z) = \frac{R_0 n_0}{\sqrt{x^2 + y^2 + z^2}}$
- Density profile integrated on the probed volume by the beam  
→ effective absorption length  $l_{\text{abs}}(N)$

$$Abs(\sigma) = \frac{k(\sigma)}{x_0 y_0} \int_d^{d+x_0} \int_{-y_0/2}^{y_0/2} \int_{-L/2}^{L/2} n(x, y, z) dx dy dz$$

$$Abs(\sigma) = k(\sigma) n_0 \frac{R_0}{x_0 y_0} \int_d^{d+x_0} \int_{-y_0/2}^{y_0/2} \int_{-L/2}^{L/2} \frac{1}{\sqrt{x^2 + y^2 + z^2}} dx dy dz$$

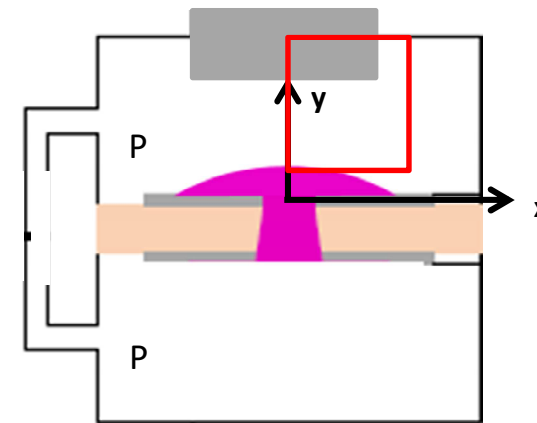
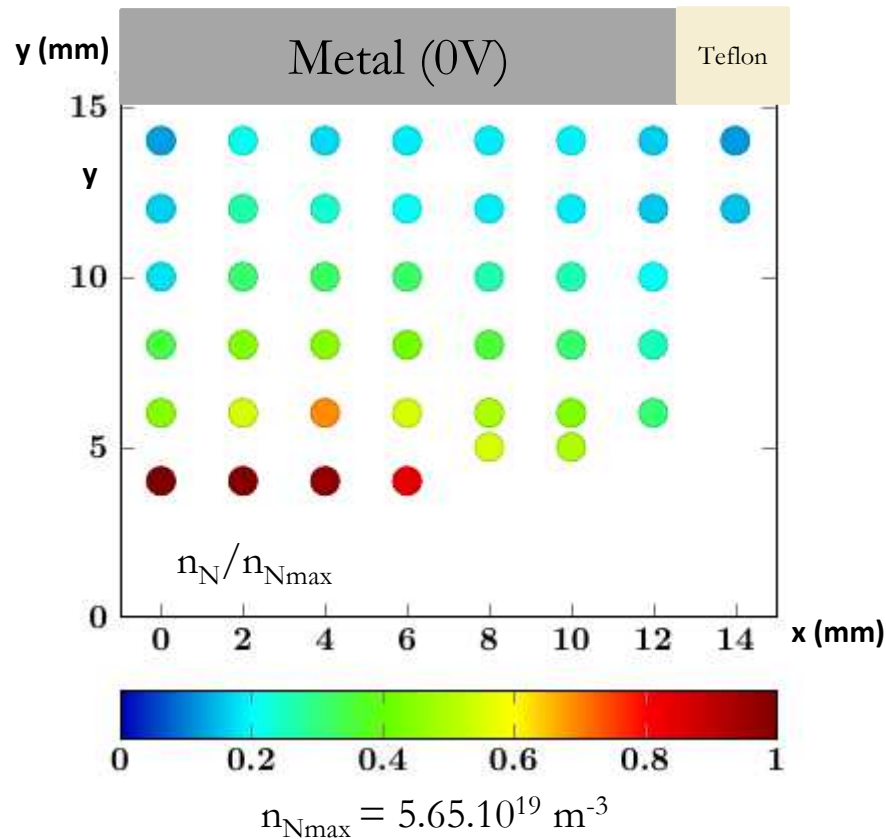
$$Abs(\sigma) = k(\sigma) n_0 l_{\text{abs}}(N)$$

- Numerical integration →  $l_{\text{abs}}(N) = 1.58 \text{ mm}$  and  $n_{\text{FTS}} = n_0 = n_N(r=R_0)$

A. Remigy et al. *J. Phys. D* **55** (2022) 105202

# Spatial mapping of N by TALIF

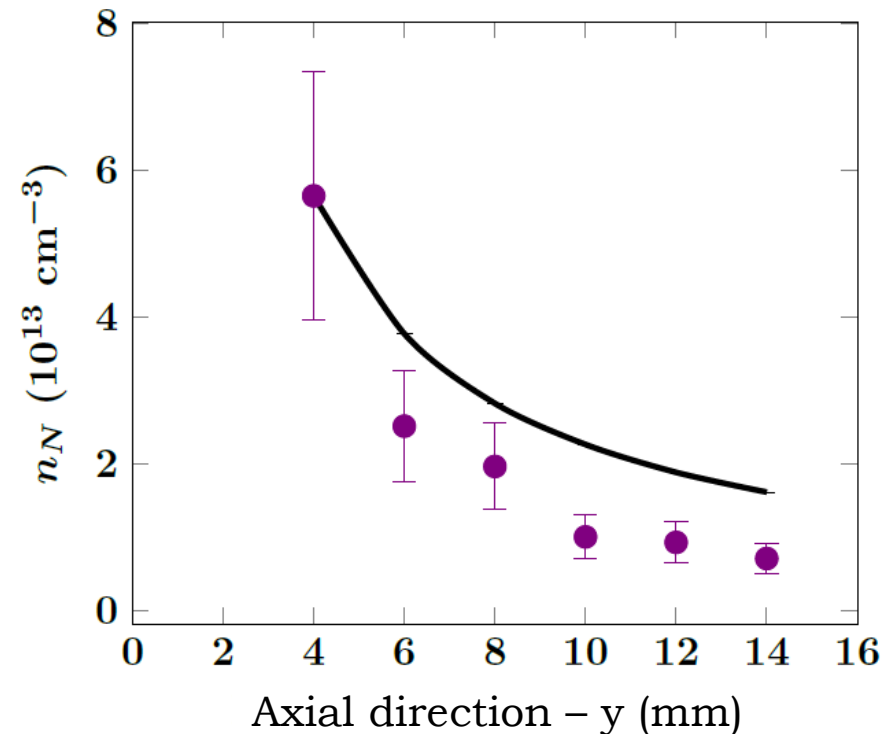
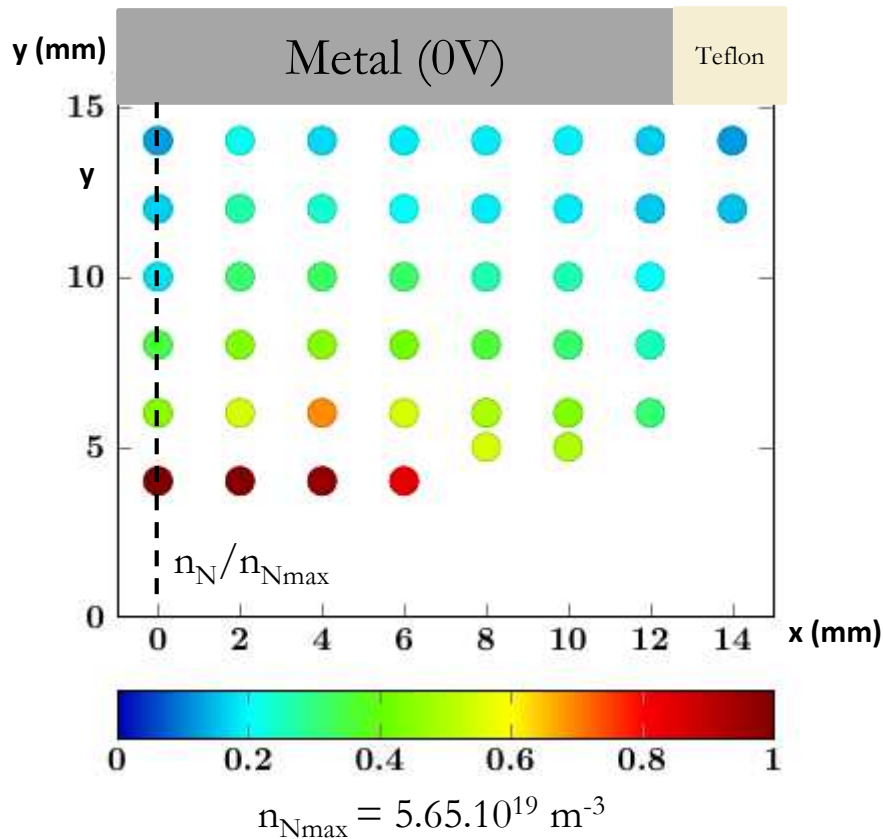
**Conditions:** 80% N<sub>2</sub> - 20% Ar, 1.6 mA, 50 mbar



- High density near the cathode surface and then fast decay

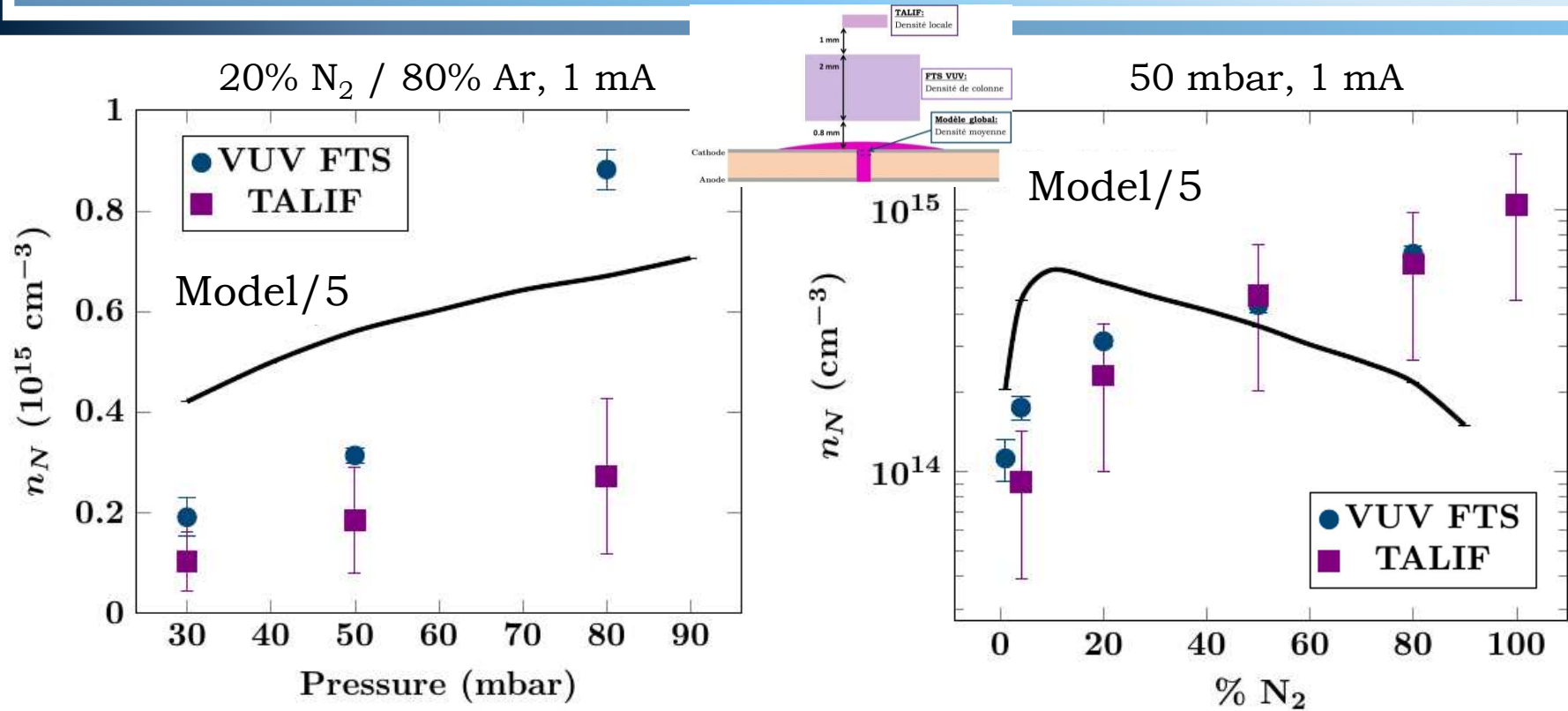
# Spatial mapping of N by TALIF

**Conditions:** 80% N<sub>2</sub> - 20% Ar, 1.6 mA, 50 mbar



- High density near the cathode surface and then fast decay
- Decrease in agreement with the diffusion model

# $n_N$ : effect of pressure and dilution

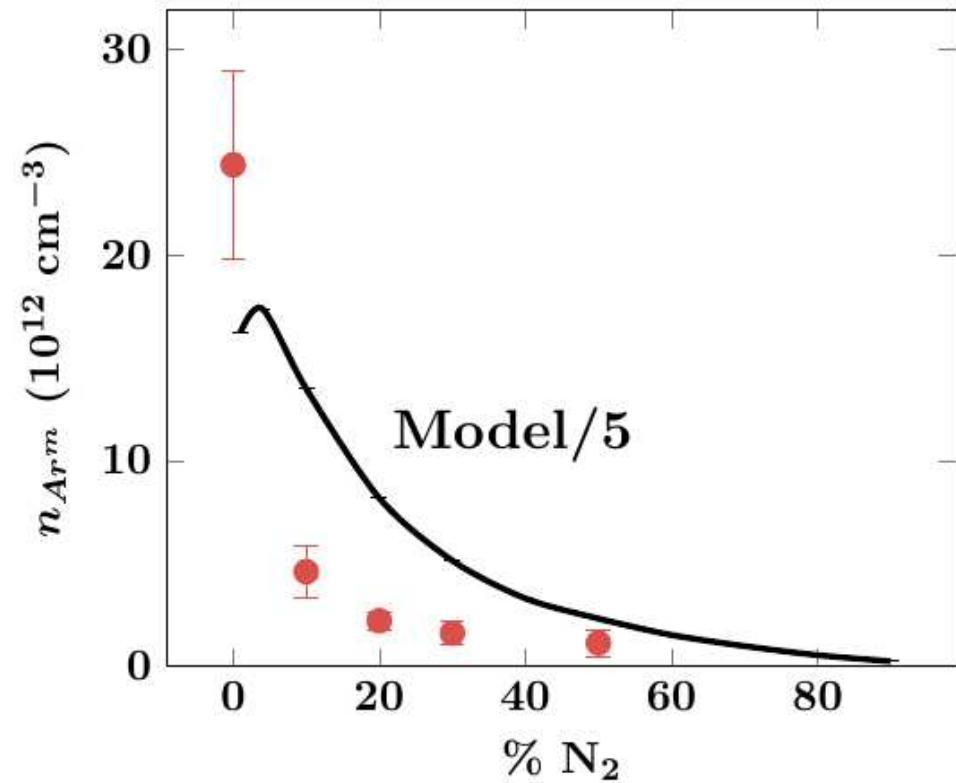
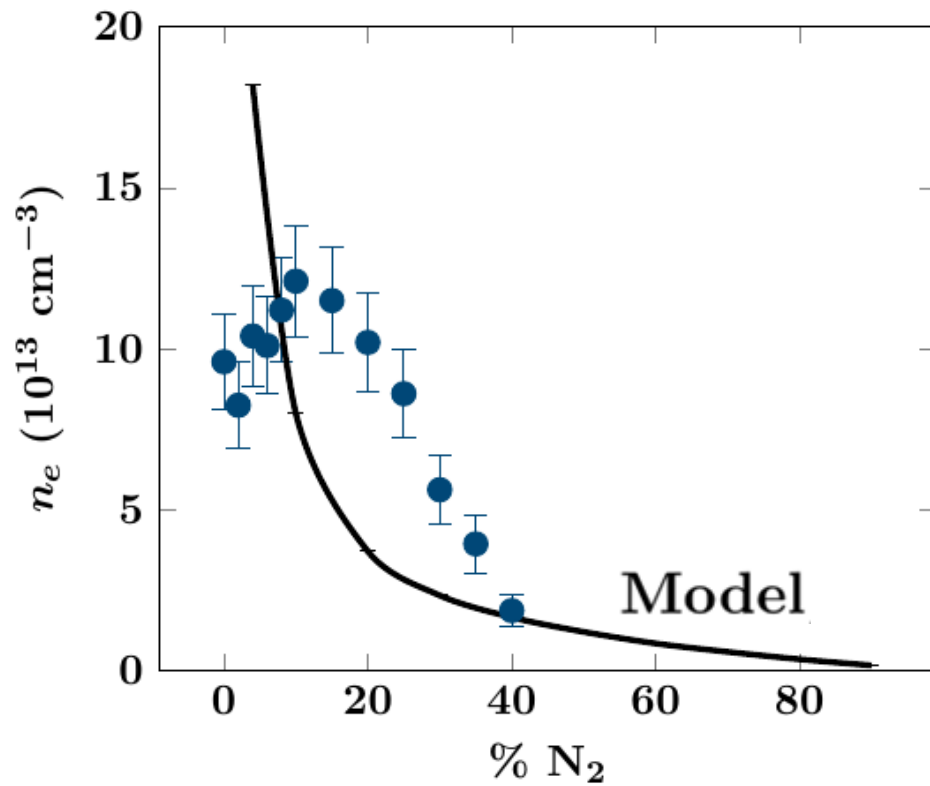


- Good agreement between TALIF and FTS; higher calculated densities
- Increase of the density with pressure and % of N<sub>2</sub>; discrepancy between the two technics at higher pressure
- Opposite trend model/experiments at high % of N<sub>2</sub>



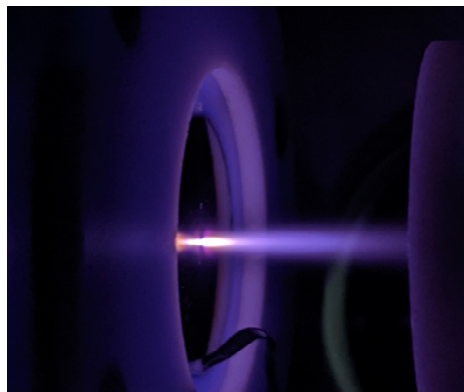
# $n_N$ : effect of dilution

50 mbar, 1 mA



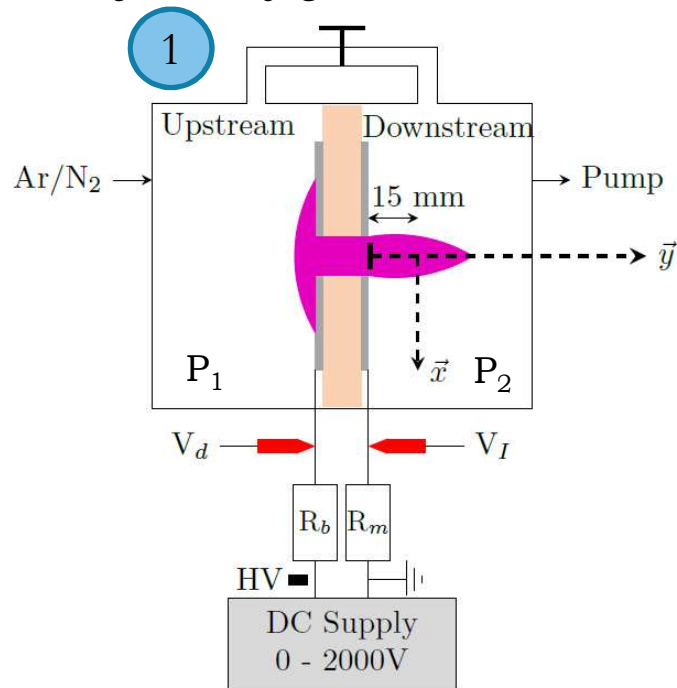
Decrease of  $n_e$  and  $n_{Ar^m}$  + increase of  $\text{N}_2^0 \rightarrow$  optimum of %  $\text{N}_2$  for  $n_N$ ?

# Study of the 1 MHCD reactor: transport of atomic nitrogen



# Experimental setups for the MHCD characterization

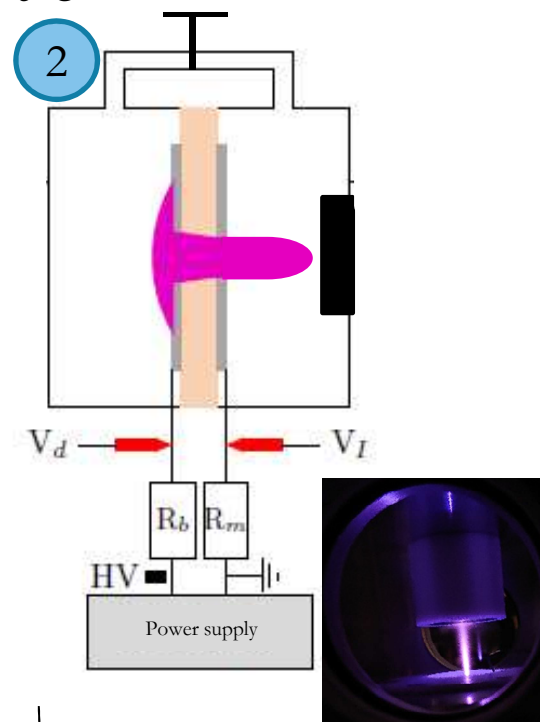
Free jet configuration



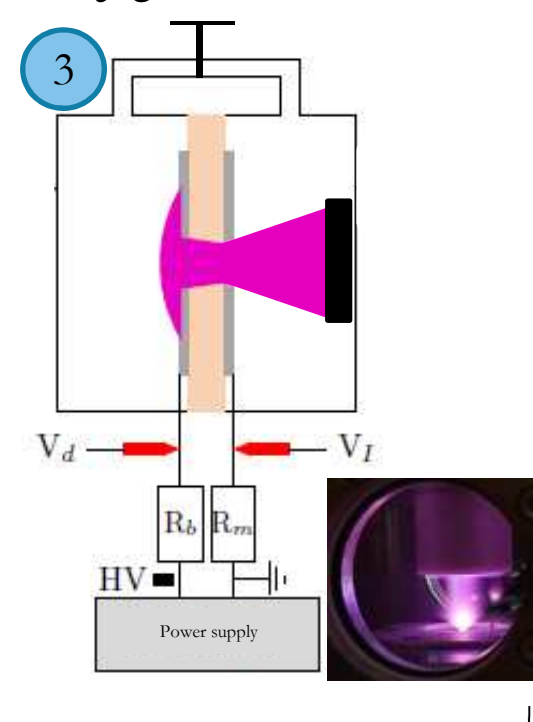
MHCD jet without a 3<sup>rd</sup> electrode

30 mbar <  $P_1$  < 110 mbar  
1 mbar <  $P_2$  < 10 mbar

Jet configuration



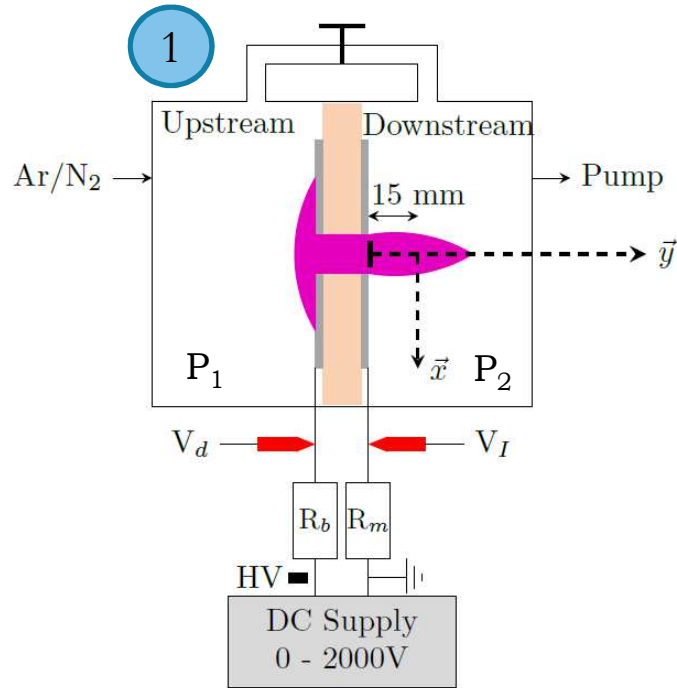
MCS D configuration



MHCD jet with a 3<sup>rd</sup> electrode:  
1.5 cm between the MHCD and the 3<sup>rd</sup> electrode  
MHCD jet / MCS D  
(Substrate holder not polarized / polarized)

# Experimental setups for the MHCD characterization

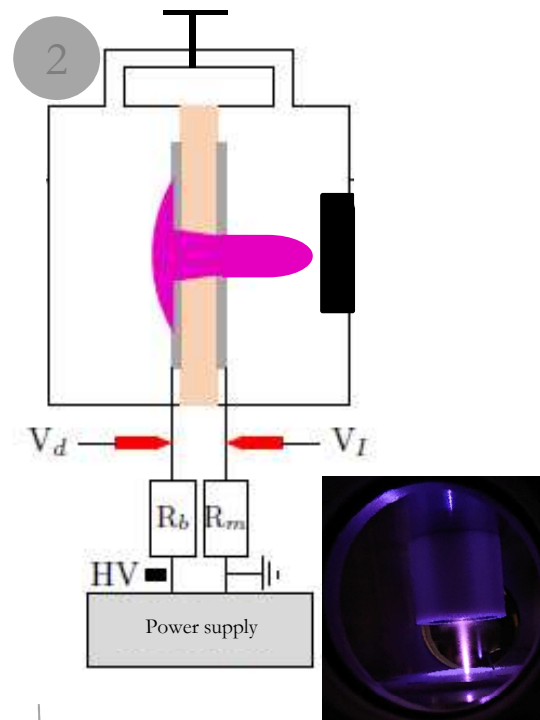
Free jet configuration



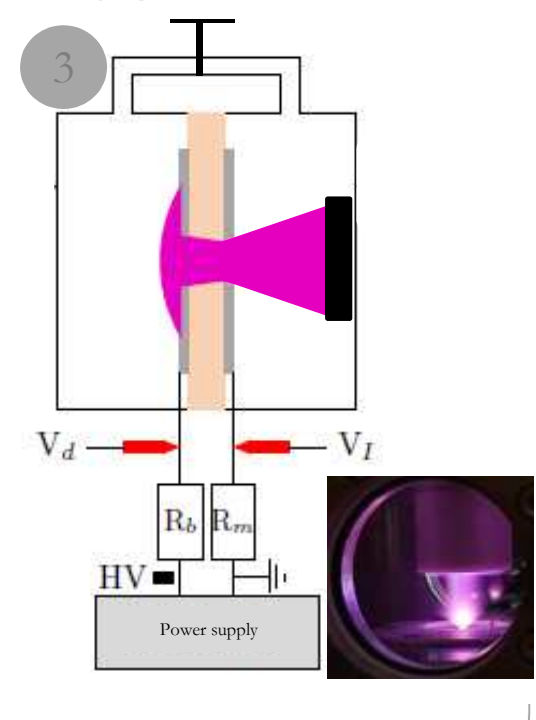
MHCD jet without a 3<sup>rd</sup> electrode

30 mbar <  $P_1$  < 110 mbar  
1 mbar <  $P_2$  < 10 mbar

Jet configuration



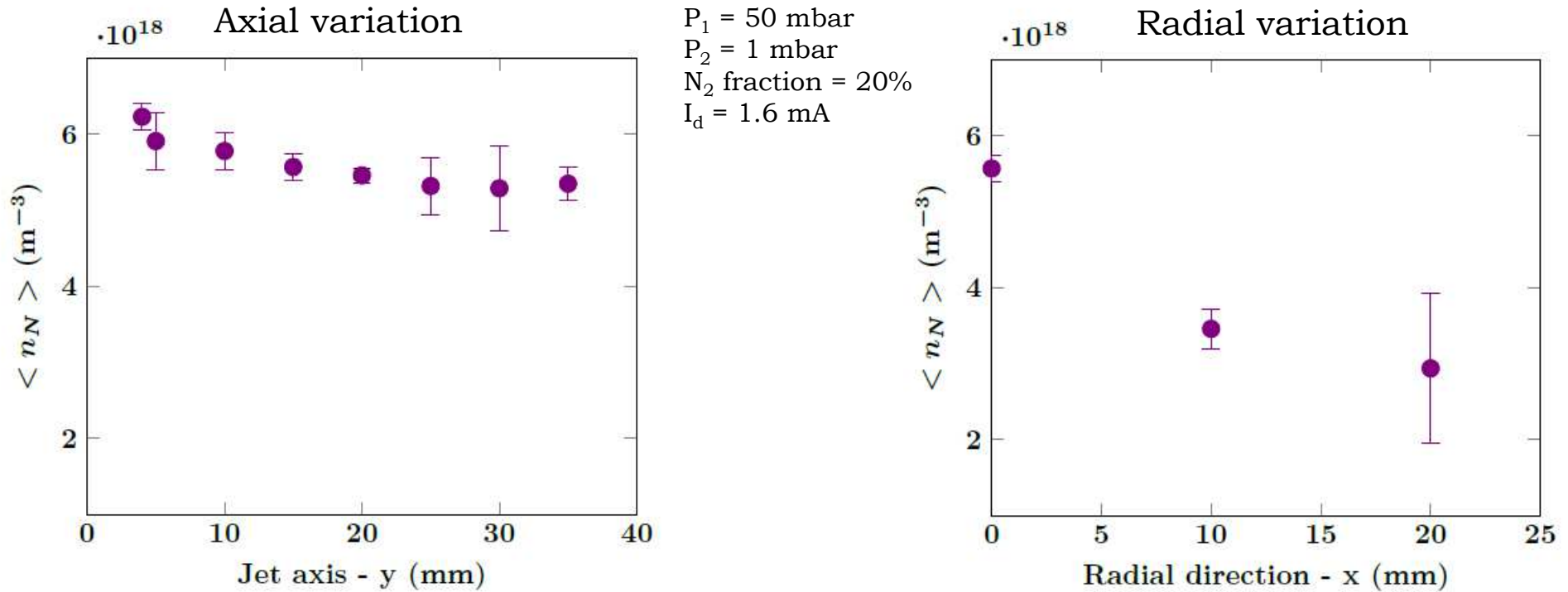
MCSD configuration



MHCD jet with a 3<sup>rd</sup> electrode:  
1.5 cm between the MHCD and the 3<sup>rd</sup> electrode  
MHCD jet / MCSD  
(Substrate holder not polarized / polarized)

# Spatial mapping of N

1



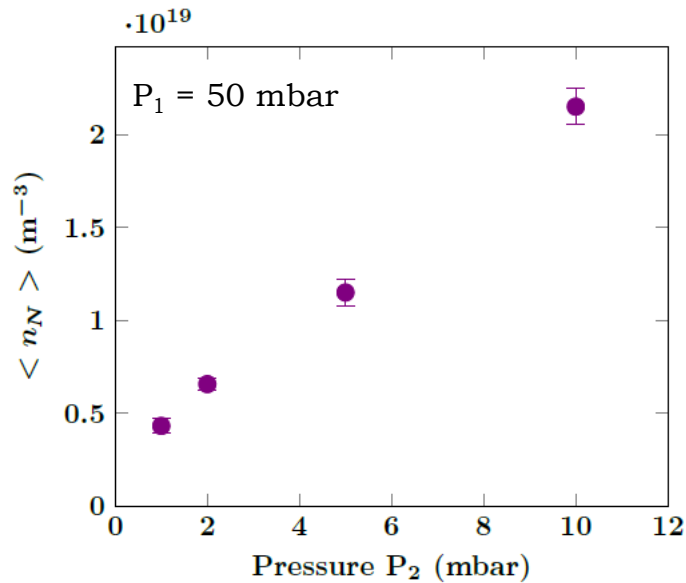
A. Remigy et al. *PoP* **29** (2022) 113508

- Density of N atoms almost constant along the jet axis: decrease of 16% over 35 mm  
→ Production in the cathodic region and transport along the anodic chamber due to the pressure differential
- Decrease of the density along the radial direction: density 2 times lower at  $x=20$  mm  
→ could be overcome using an array of holes (MHCDs in parallel)



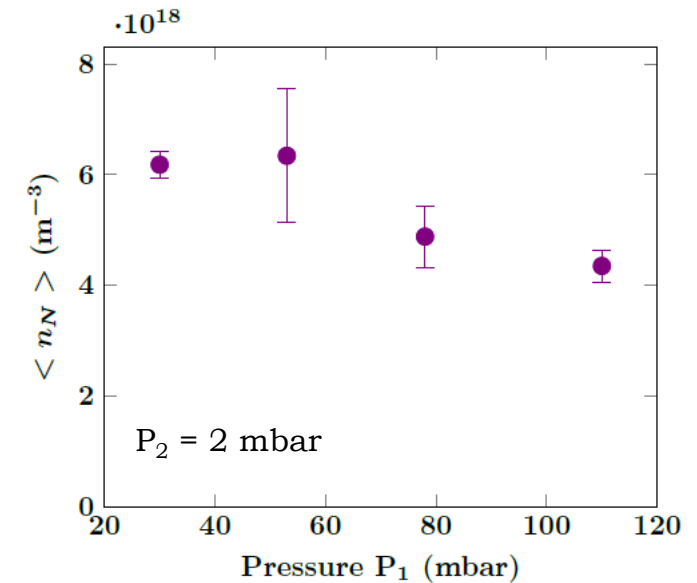
# Effect of the pressures

1



-  $n_N$  4 times higher when  $P_2$  increases by a factor of 10

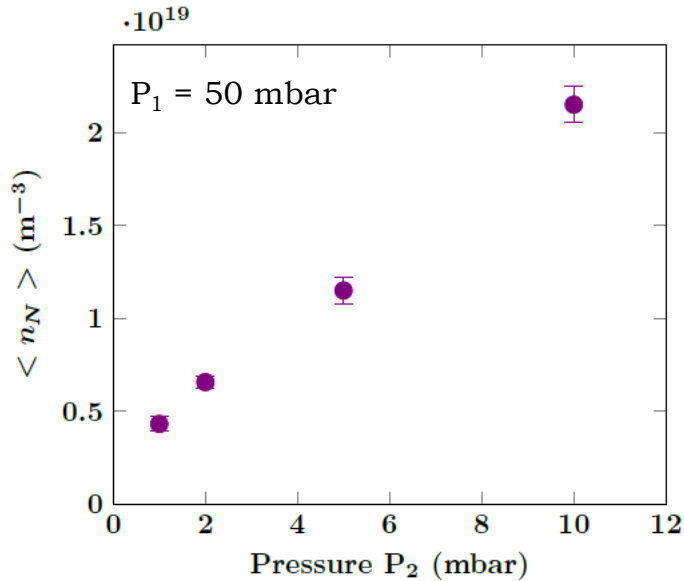
- The time spent by the gas mixture in the cathodic region increases with  $P_2$



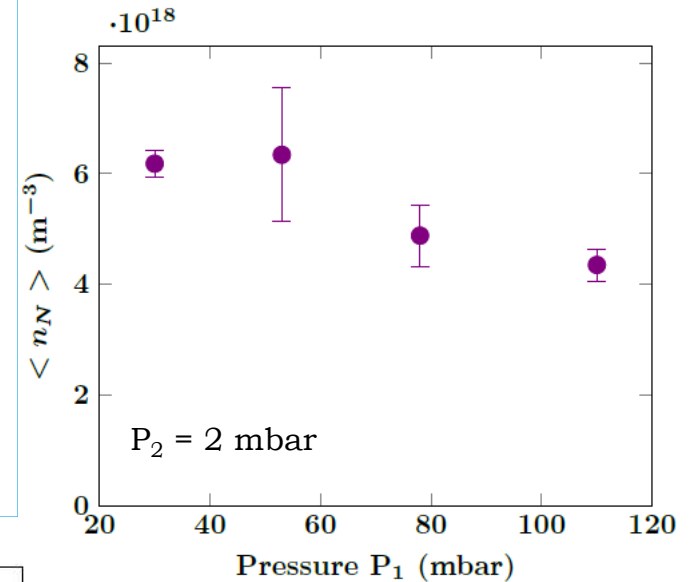
-  $n_N$  decreases with  $P_1$   
- Effect of  $P_1$  lower than that of  $P_2$  (decrease of 30% over a range of pressure of 80 mbar)  
- Decrease of the N atom density with the increase of the pressure differential, in both cases  $\rightarrow$  residence time?

# Effect of the pressures

1

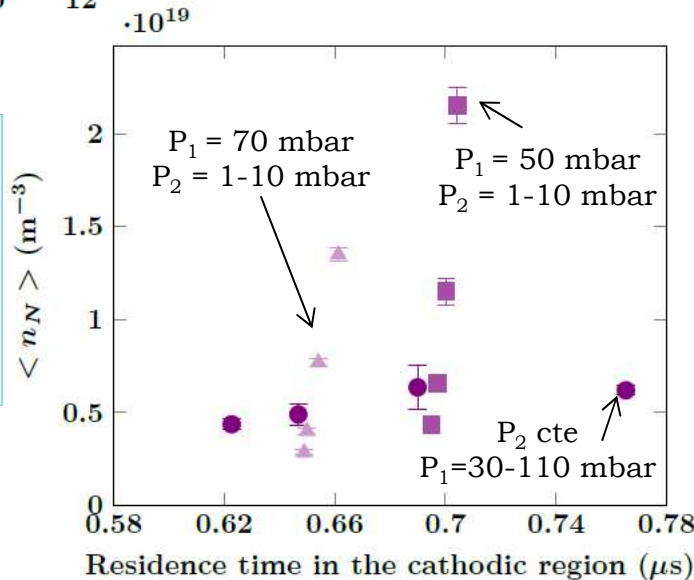


- No general correlation between the residence time and  $n_N$
- Role of the residence time negligible even if for  $P_2$  cte, effect probably compensated by a higher  $n_N$  at higher pressure
- Larger impact on  $n_N$  of  $P_2$ , related to the jet turbulences



-  $n_N$  4 times higher when  $P_2$  increases by a factor of 10

- The time spent by the gas mixture in the cathodic region increases with  $P_2$

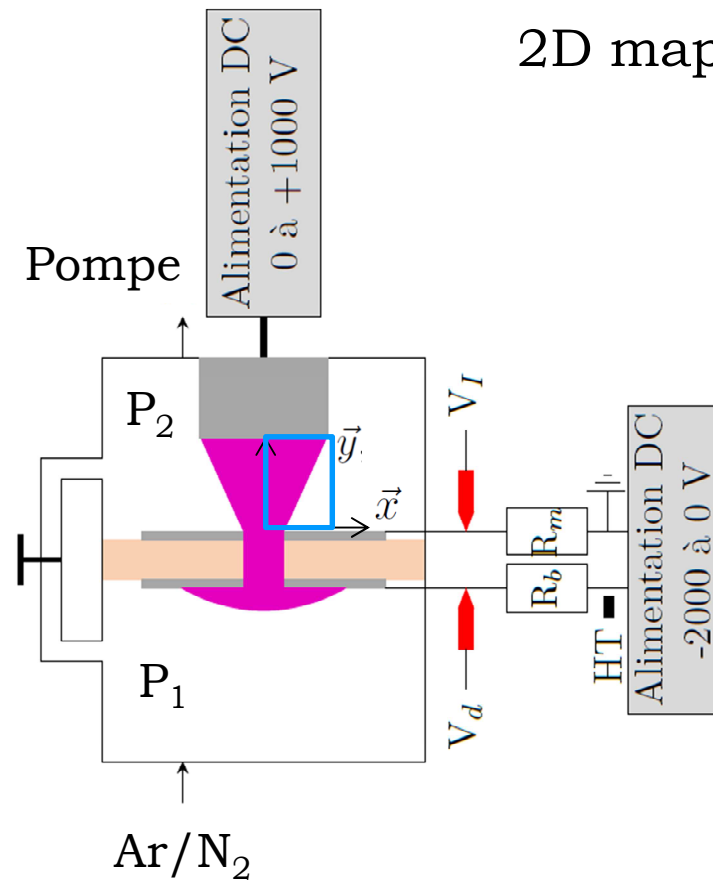
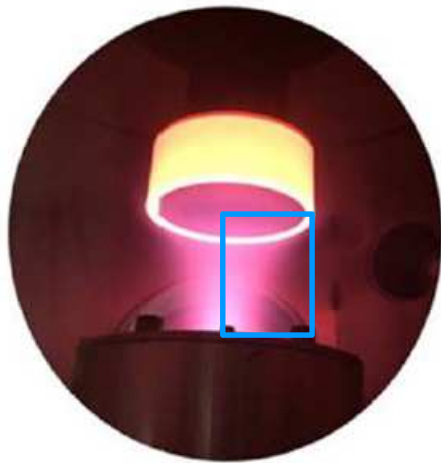


- $n_N$  decreases with  $P_1$
- Effect of  $P_1$  lower than that of  $P_2$  (decrease of 30% over a range of pressure of 80 mbar)
- Decrease of the N atom density with the increase of the pressure differential, in both cases  $\rightarrow$  residence time?

# $n_N$ in the deposition chamber

2 3

2D mapping of  $n_N$  by TALIF

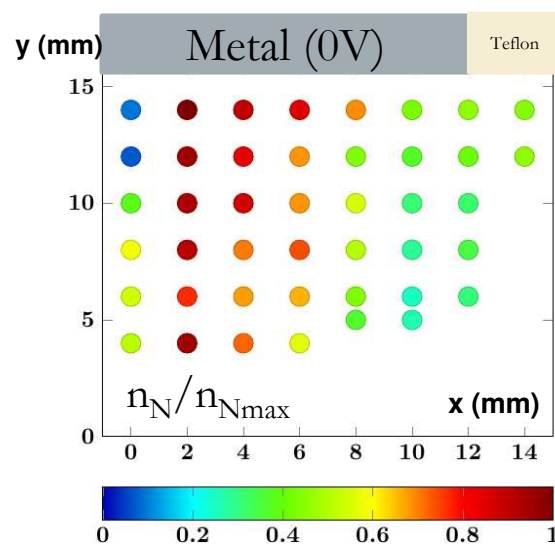


*Configurations jet + MCSD*

# Spatial mapping of N: jet configuration

2

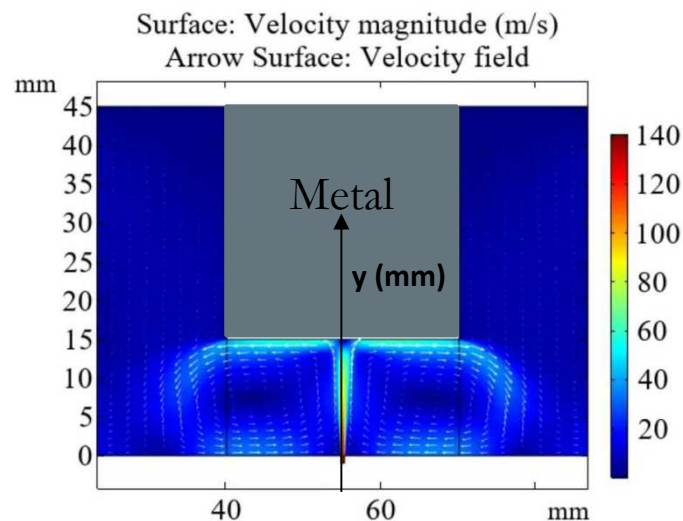
**Conditions:** 80% N<sub>2</sub> - 20% Ar, 26 sccm, 30 mbar – 10 mbar



$$n_{N_{\max}} = 2,99 \cdot 10^{19} \text{ m}^{-3}$$

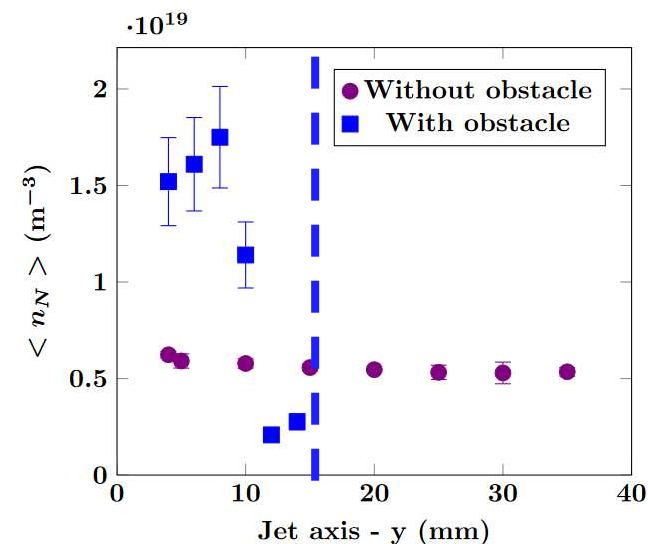
$$I_d = 1.6 \text{ mA}$$

$$I_{3^{\text{ème}} \text{ électrode}} = 0 \text{ mA}$$



*O. Gazeli, University of Cyprus, PV Technology*

**Comsol simulation:** 100% Ar

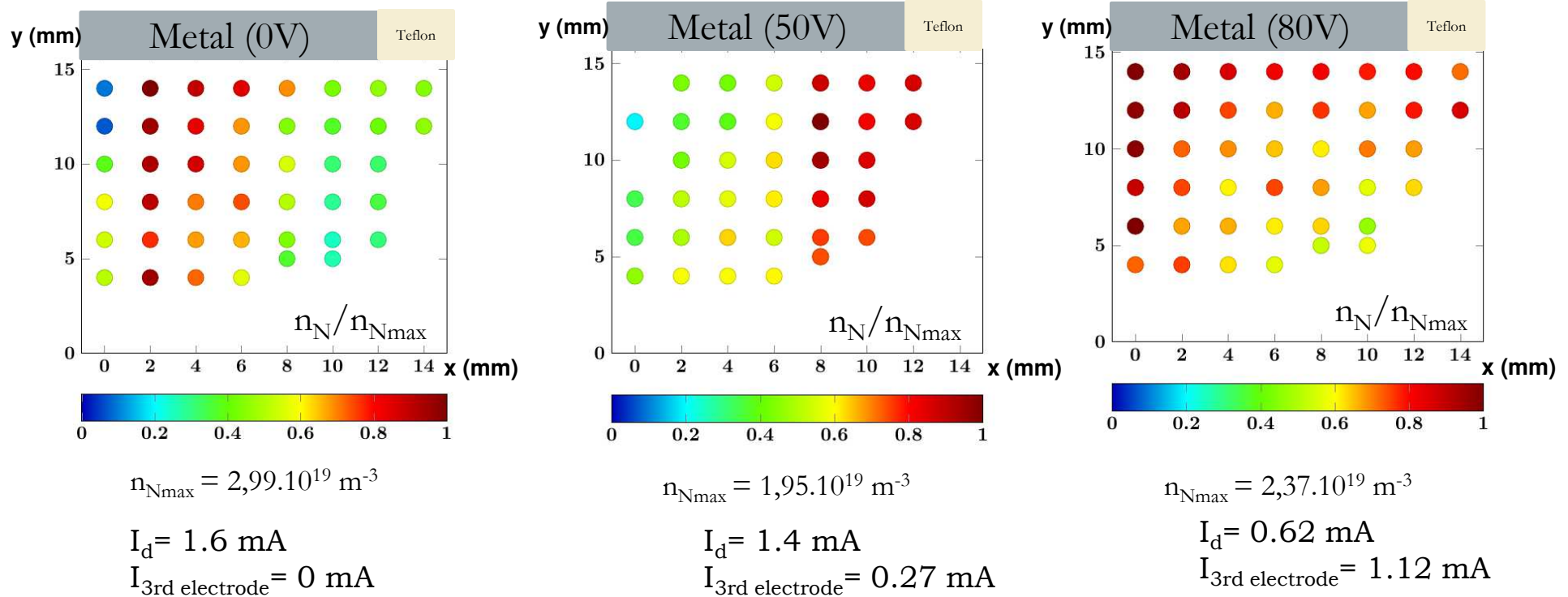


- With an obstacle: depletion in the center → gas flow
- In that case we do not have a film deposition

# Spatial mapping of N: MCSD

3

**Conditions:** 80% N<sub>2</sub> - 20% Ar, 26 sccm, 30 mbar – 10 mbar



- Mode transition required to homogenize the density
- Almost homogenous density over the whole substrate



# Conclusion

- MHCD is an effective way to produce high densities of N atoms and cover a high area substrate homogeneously → low cost process for h-BN deposition
- Small impact of  $P_1$  on  $n_N$ , larger effect of  $P_2$ : great impact of fluid effects, more than the expected effect of the resident time
- Presence of N atoms near the substrate not enough for a deposition : bias needed
- 3<sup>rd</sup> electrode polarized with a voltage high enough to have more current flowing through the second anode → homogeneous density on the substrate + dissociation of boron precursor?

# Perspectives

- Future deposition experiments: increase of the pressure in the deposition chamber ( $P_2$ ) and variation of the bias on the substrate holder
- Improvement of the global model: chemistry of discharge  $\rightarrow$  vibrational levels of  $N_2$ , eedf in presence of  $N_2$   $\rightarrow$  Boltzmann's solver, treatment of the wall losses  $\rightarrow$  analytical model of the sheath (+ comparison to PIC simulations)
- Focus on B atoms (mapping in the deposition chamber) + modelisation of the gas flow  $\rightarrow$  design of the future reactor (new MHCD source, new heating system of the substrate holder)



# Thanks for your attention

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Alice Remigy is looking for a post-doc position from August 1<sup>st</sup> 2023:

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